

Lab on a Chip and Microfluidics

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d'électronique



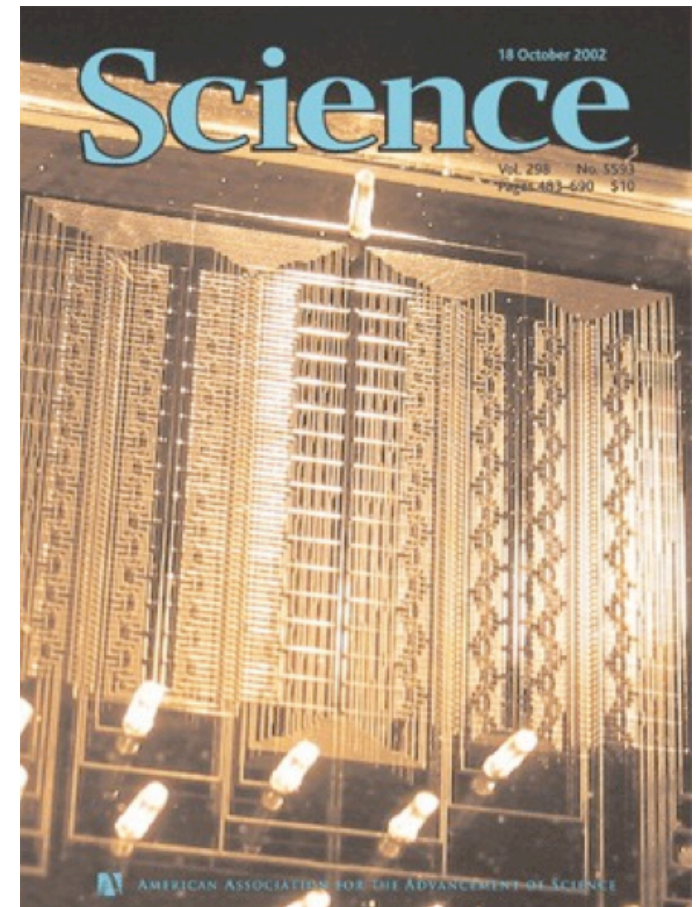
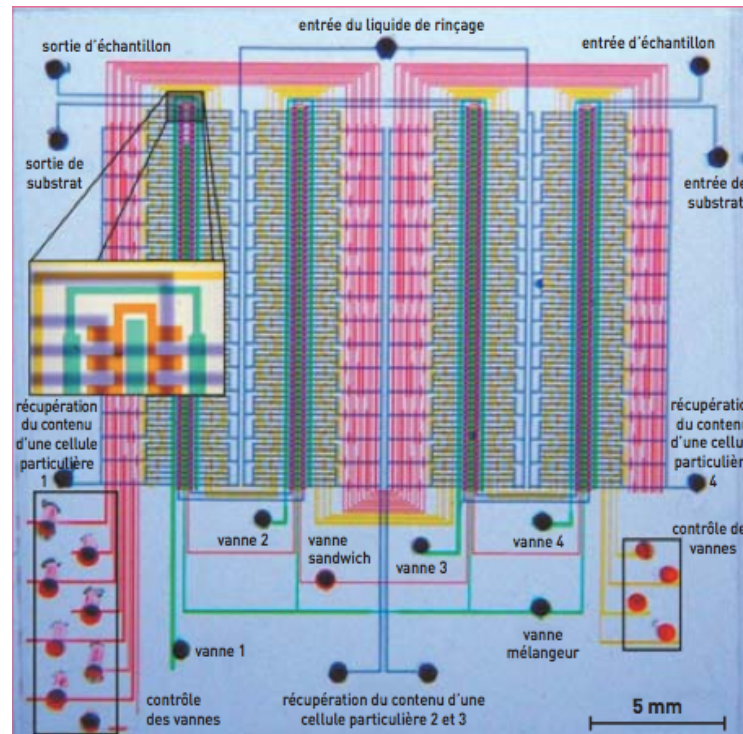
Part II. Lab On Chip technologies

Lab On Chip

BioMEMS and microfluidics have started in 2000's

The idea is to use what has made the success of microelectronics and MEMS to biochemical engineering and cellular biology.

- Miniaturisation**
- Integration**
- Parallelism**
- Batch Fabrication**

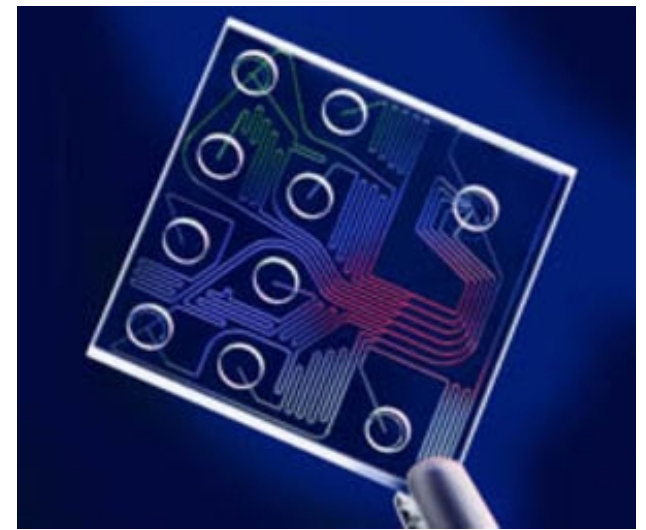


Lab On Chip

Lab on chip (laboratories on chip)

μ TAS (micro Total Analysis System)

Point of Care



Functions operated on a Lab On Chip

Fluid transport (Electro-osmosis, Electro-phoresis, Hydrostatic pressure)

Preparation (Heating, Filtration, Extraction)

Separation (diffusion, electrophoresis, isoelectric focusing)

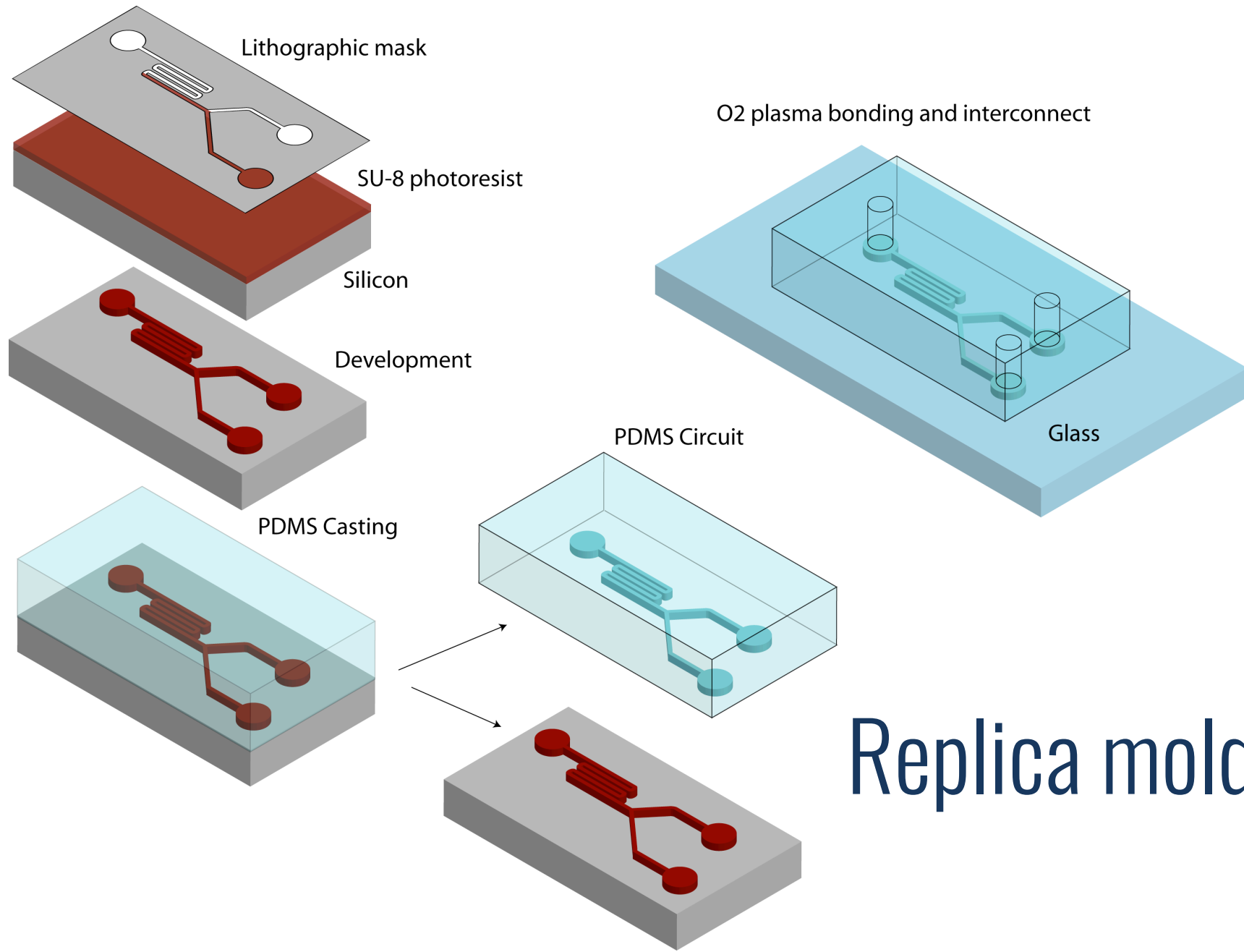
Mixing (diffusion, forced mixing)

Reaction (culture chambers, markers)

Detection (Chemiluminescence, electrochemiluminescence, fluorescence, Electrochemical detection, mass spectroscopy, Surface Plasmon Resonance)

How these devices are made?

Microfluidic Technologies PDMS on glass



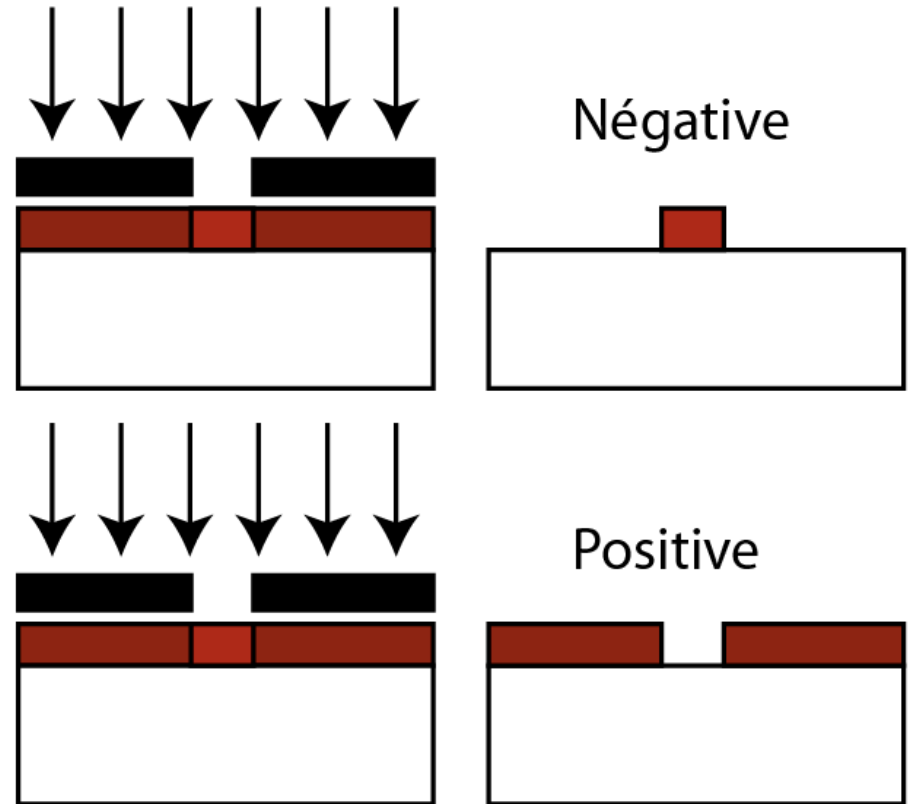
SU-8 photoresist

SU-8 photoresist is a negative photoresist that has the particularity to produce structures with high aspect

Microelectronic PR : 100nm to 2µm thick
S1818, S1805, AZ2020, ZPN 1150

SU-8 : from 2µm up to 200µm

900 Euro/500ml



SU-8 photoresist

Composition :

Resist : epoxy (8 epoxy groups)

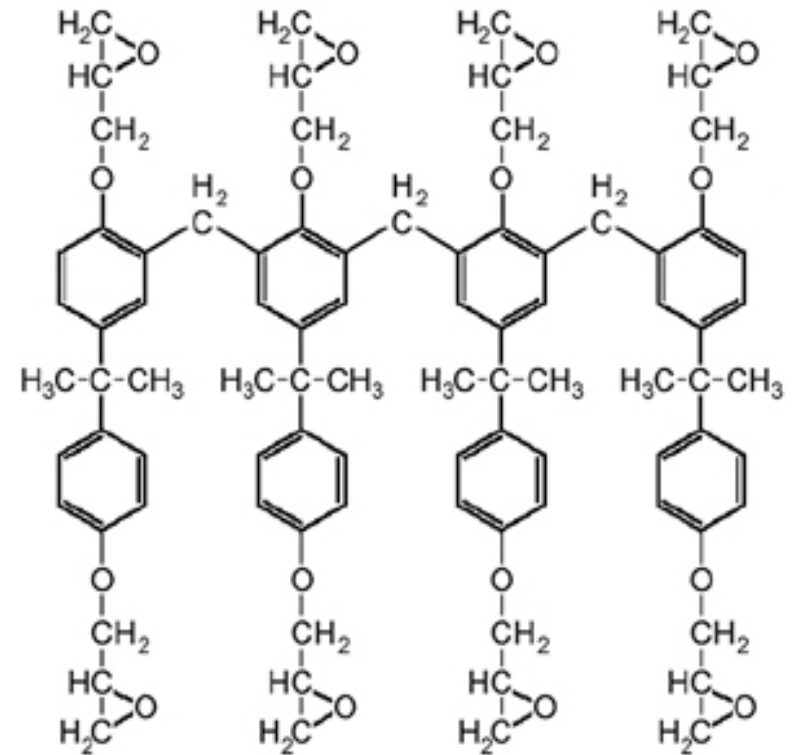
Solvent : Gamma butyrolactone

Photo initiator

Developer : 1-Methoxy-2-propanol acetate

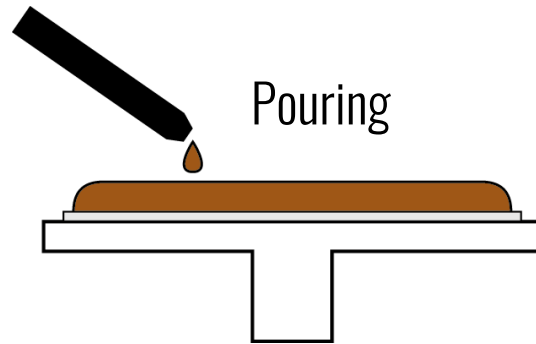
Photosensitivity with triarylsulfonium/hexafluoroantimonate
(CYRACURE UVI)

- High thermal stability ($T_g > 200\text{ }^\circ\text{C}$).
- Low UV absorbance (high thicknesses)

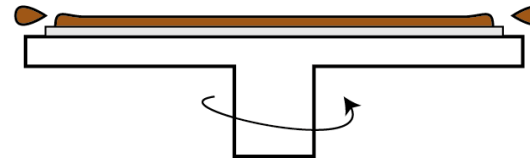


SU-8 photoresist

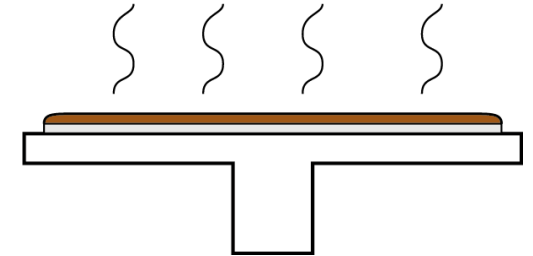
Spin Coating



Rotation 3000 RPM



Baking



Baking, with slow temperature ramps, skin effect

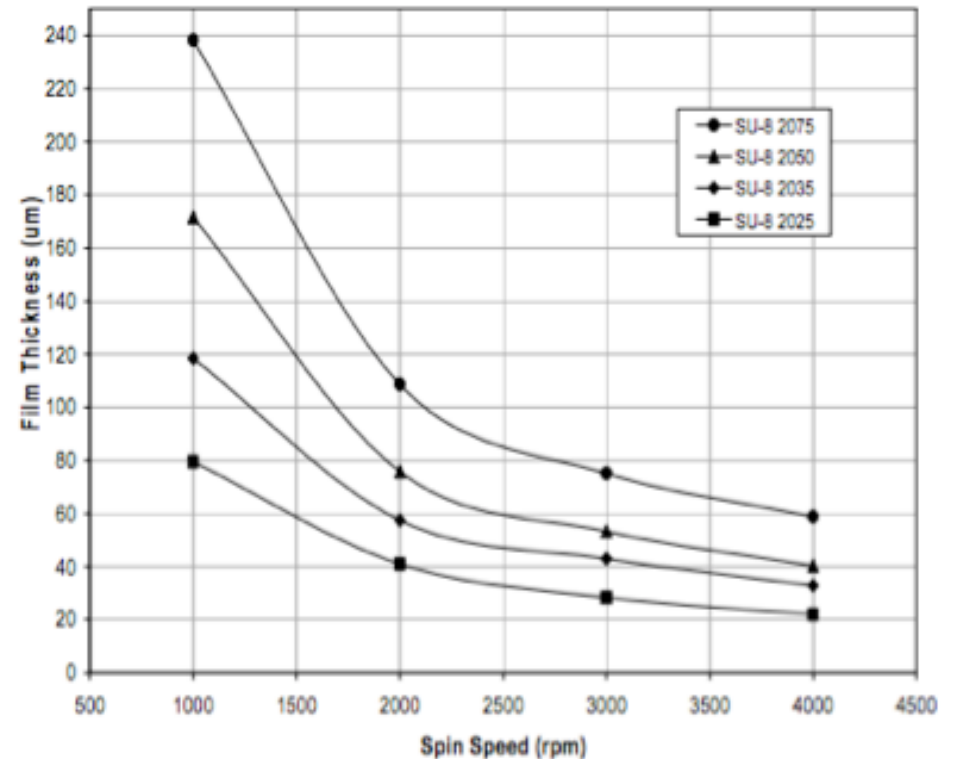
UV exposure (365 – 435nm) + Filter

Photolyse $\text{Ar}^+\text{Sb-F}_6 \rightarrow \text{H}^+\text{Sb-F}_6$ (strong acid)

Pots exposure bake: catalysis of the cationic polymerisation and cross linking

Developpement : PGMEA

Rinse IPA



SU-8 photoresist



SU8 on 3 inches wafer

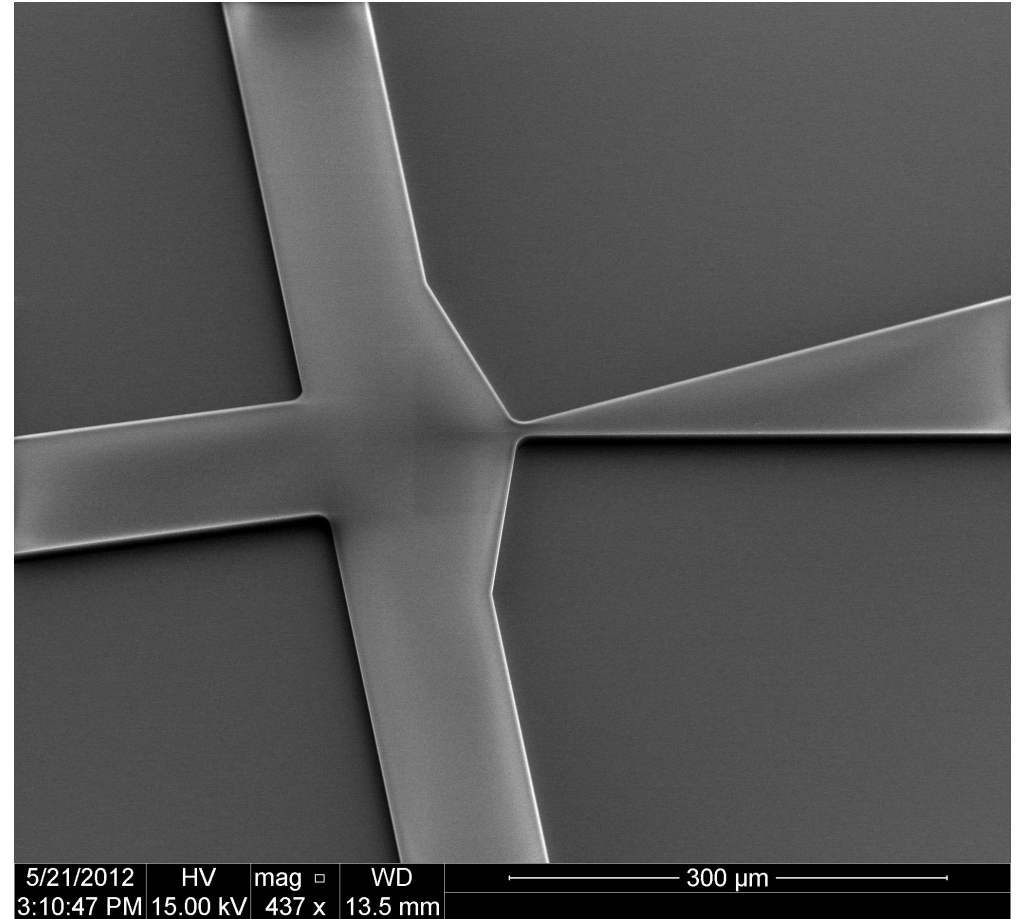
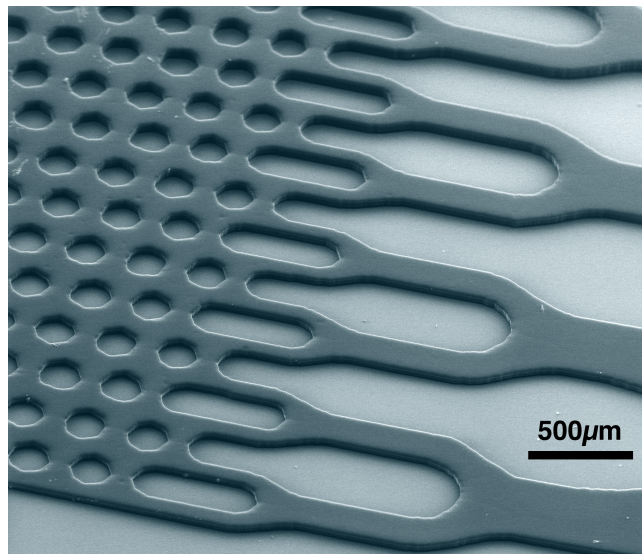
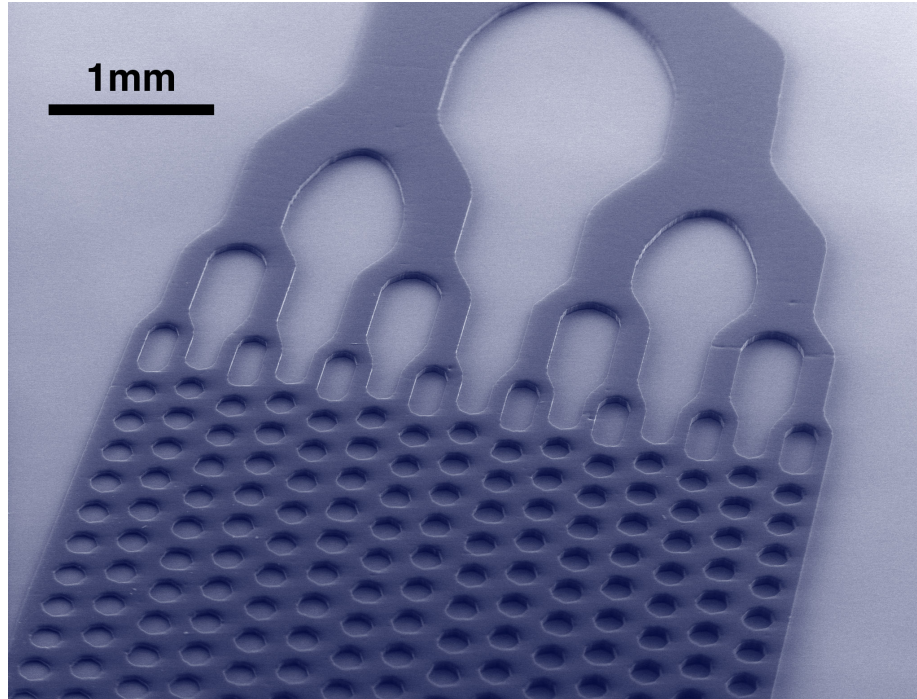


Spin coater



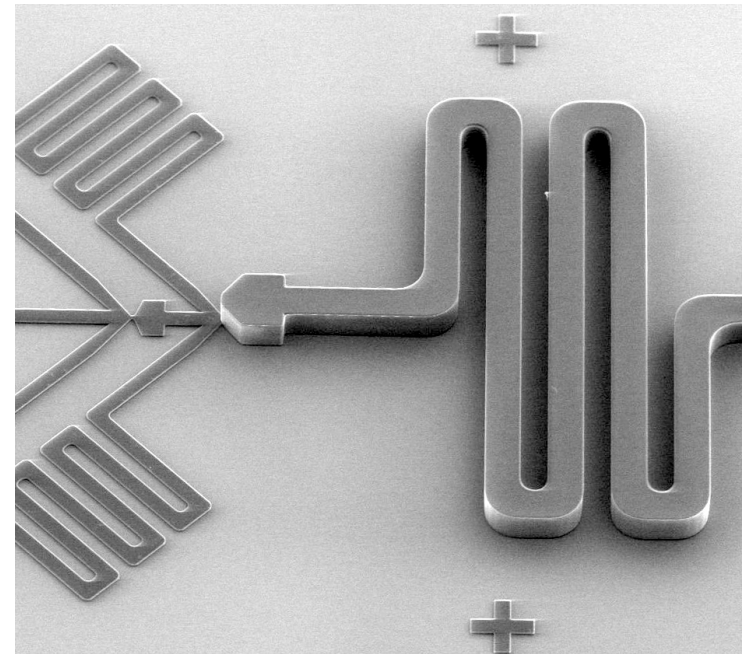
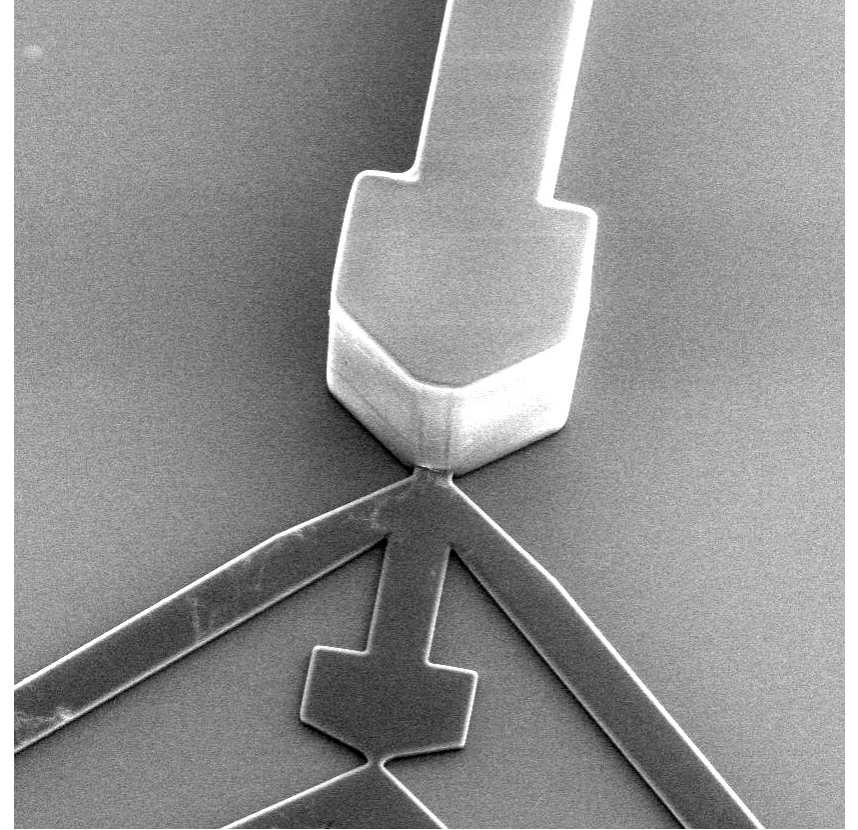
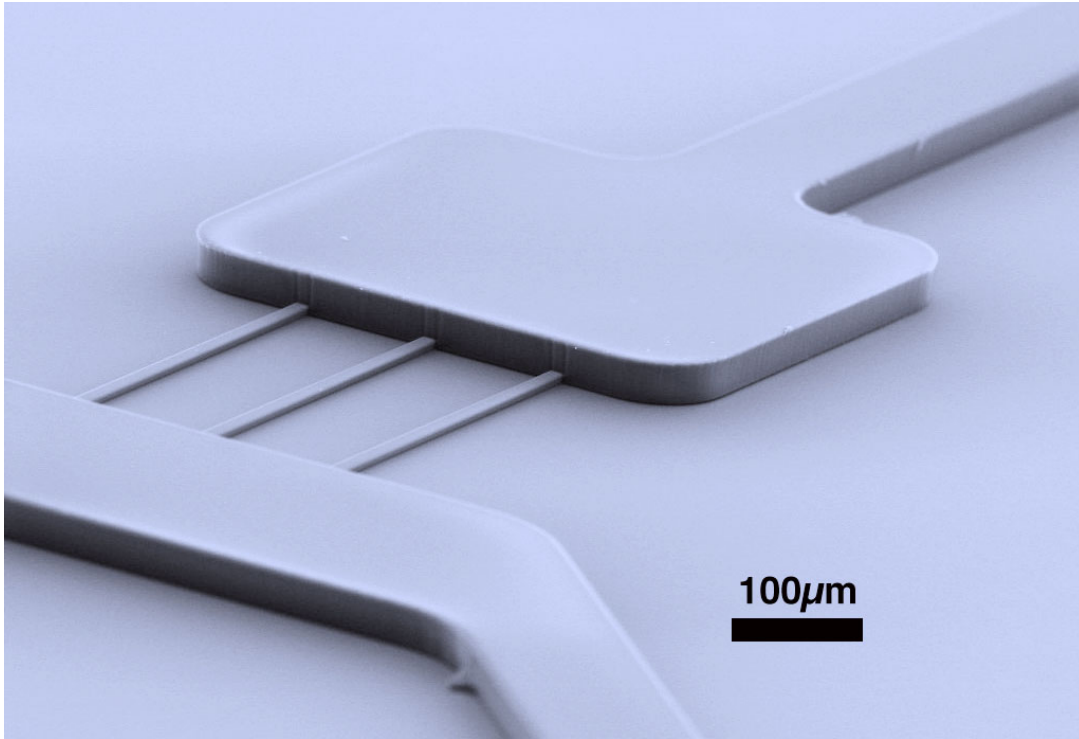
Hot plate

SU-8 photoresist

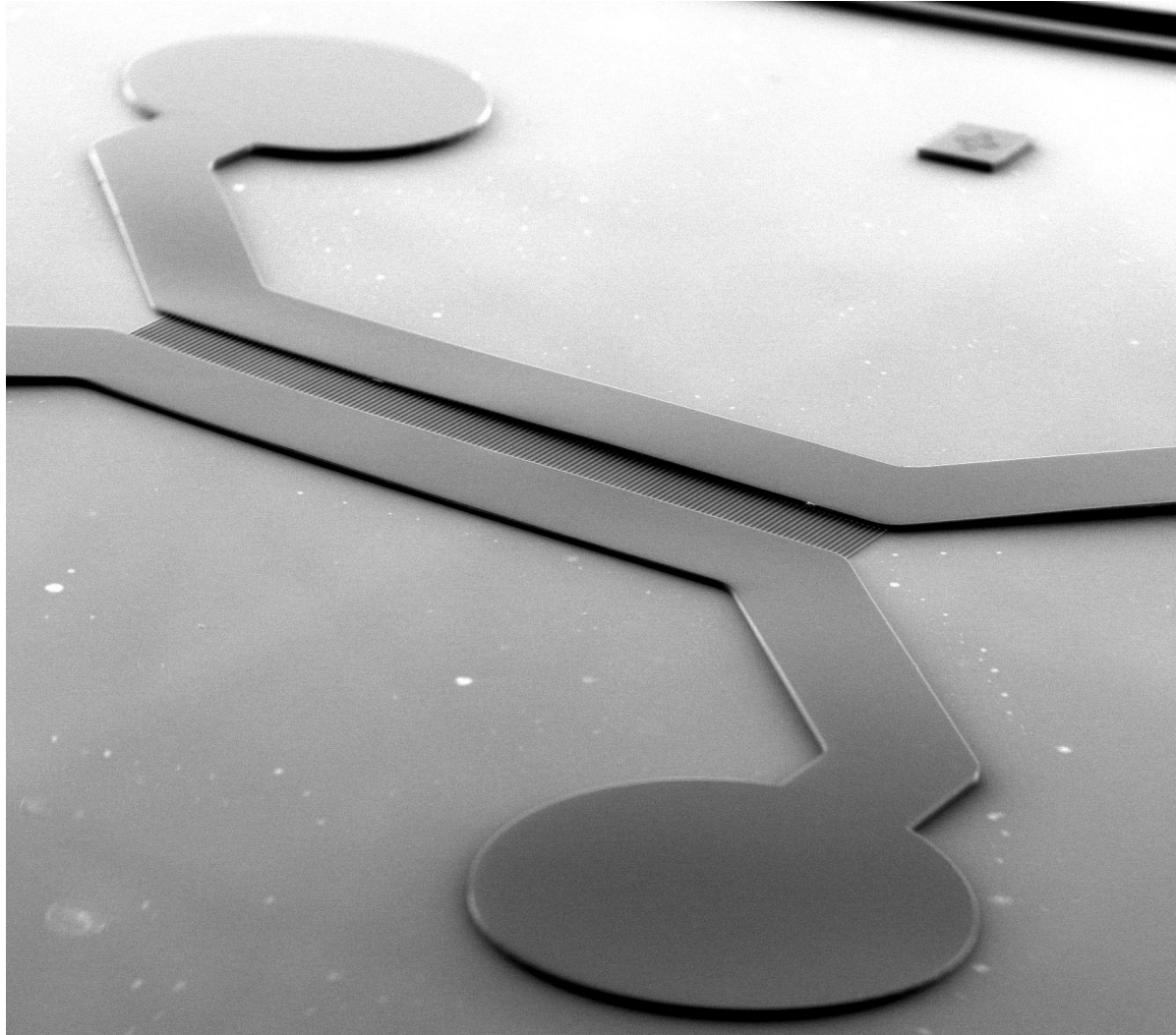


SU-8 photoresist

Dual thickness

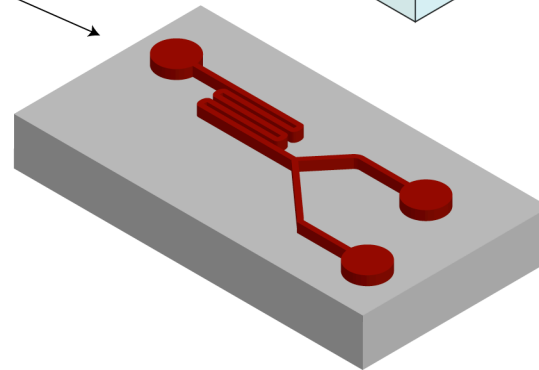
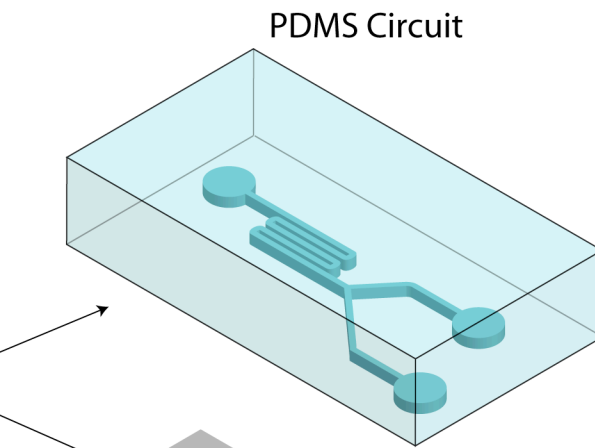
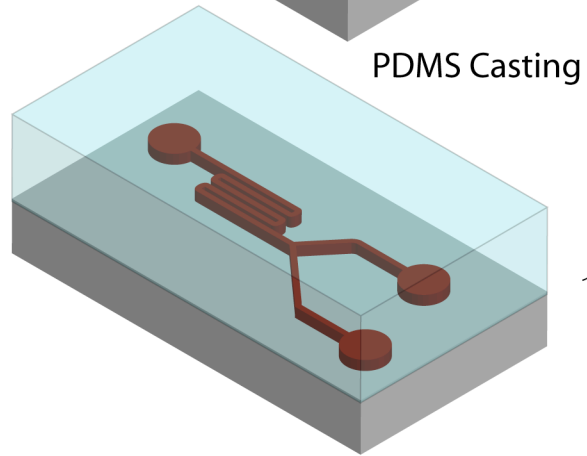
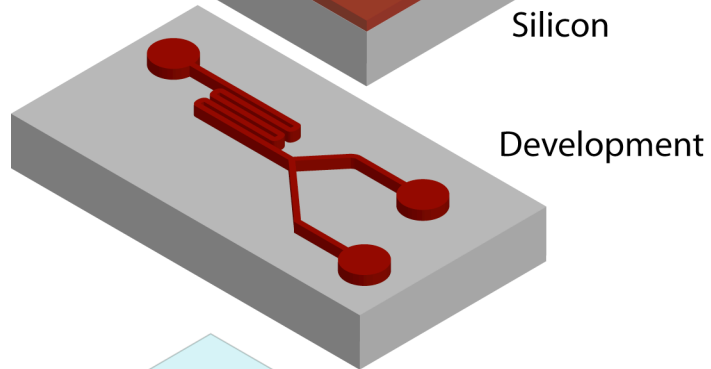
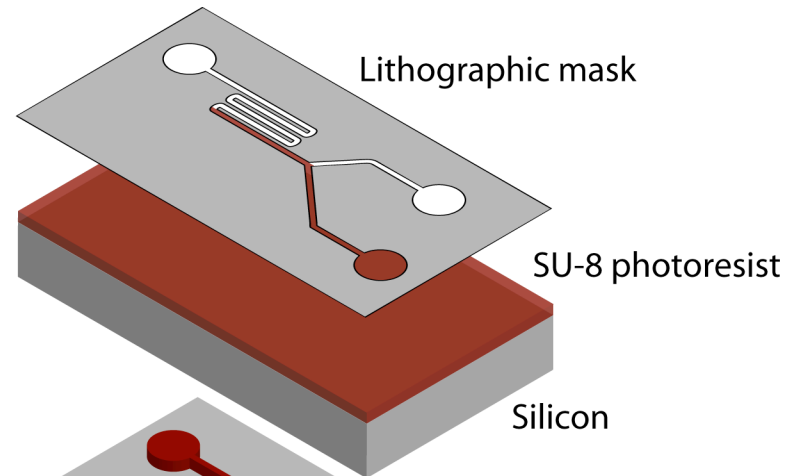


SU-8 photoresist

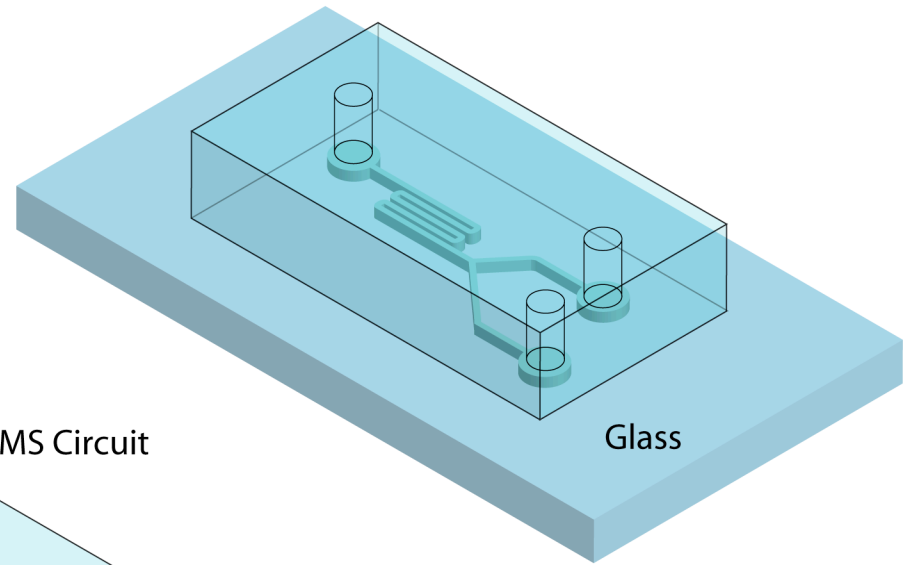


Microfluidic circuit for cell culture

Microfluidic Technologies PDMS on glass



O₂ plasma bonding and interconnect



Replica molding

PDMS Polydimethylsiloxane

Can be found in Coca cola and shampoos

PDMS is a silicone polymere

Properties

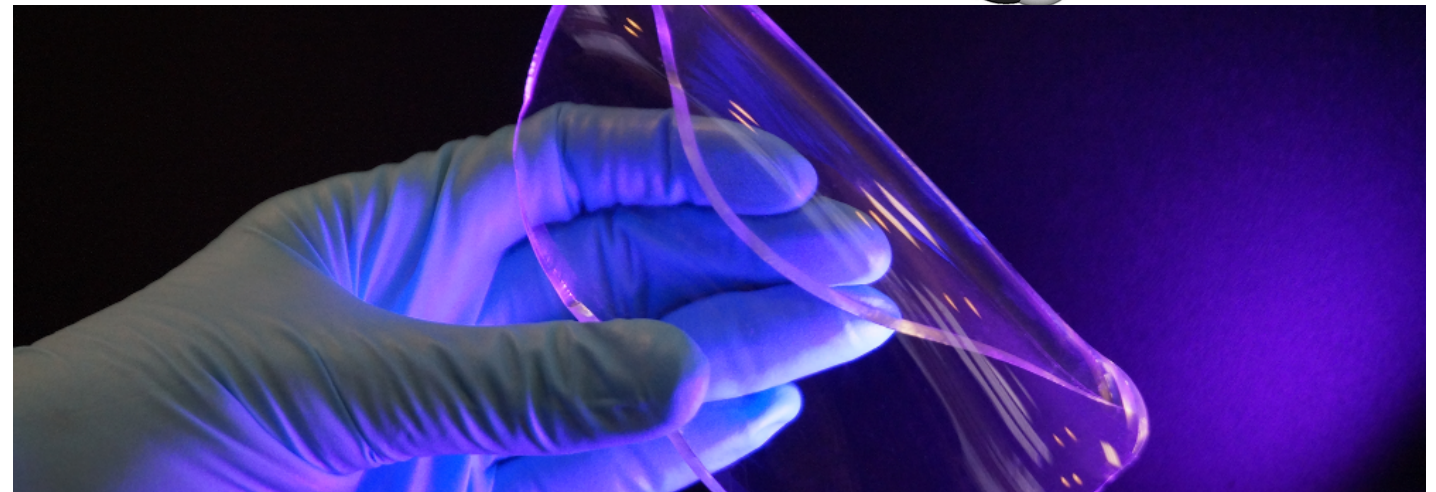
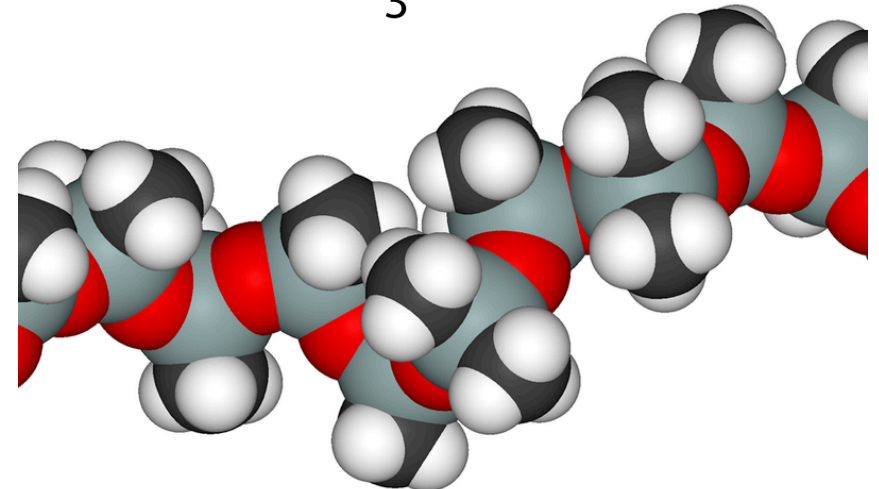
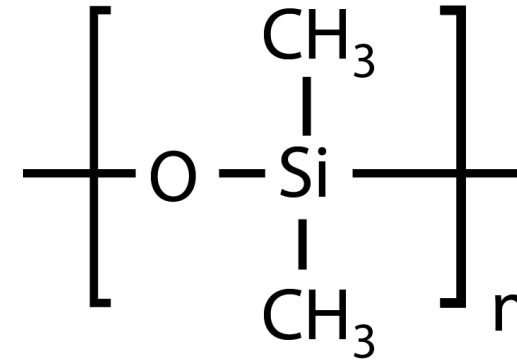
Hydrophobic

Transparent

Soft (E=1Mpa)

Diffusion (of gazes)

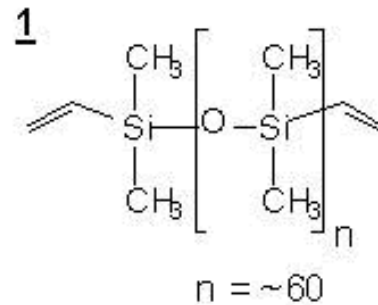
Bonding



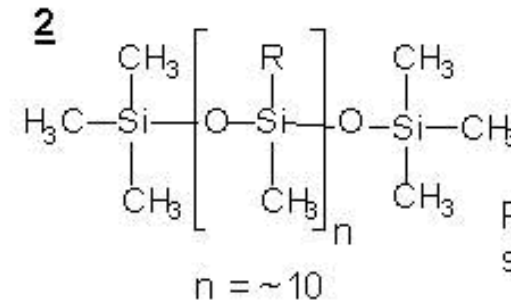
PDMS

PDMS is a viscous liquid
That becomes solid by
reticulation

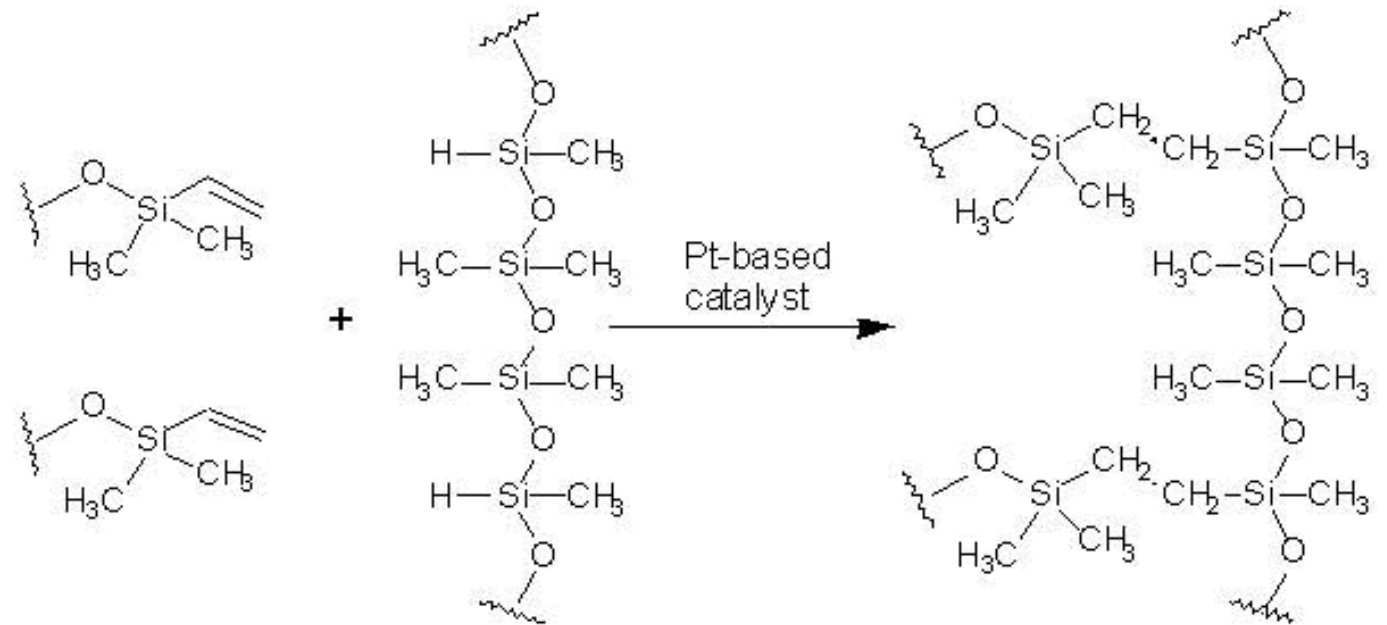
siloxane oligomers



siloxane cross-linkers



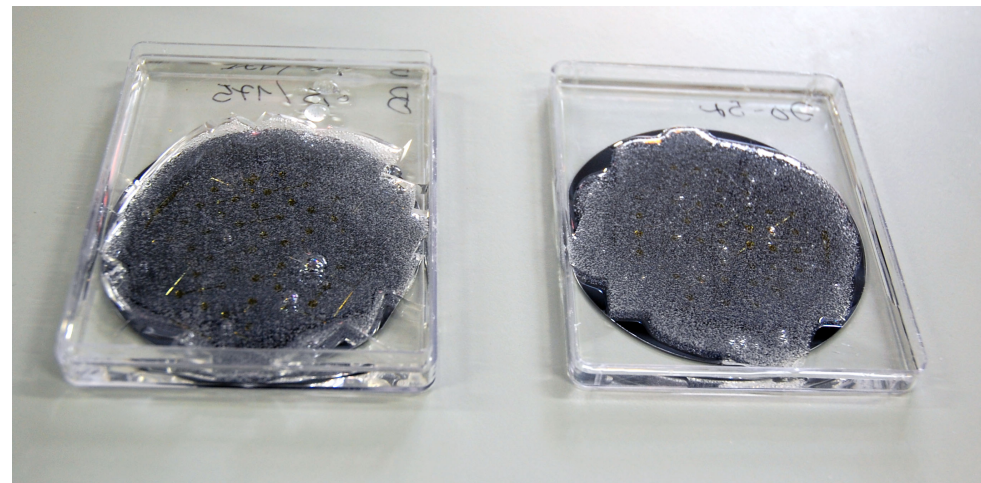
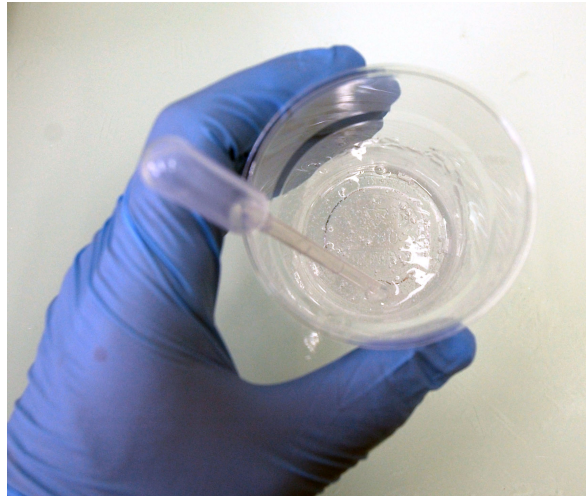
R is usually CH_3 ,
sometimes H



PDMS process

Mixing PDMS + hardener 9:1

Molding on wafer



PDMS process

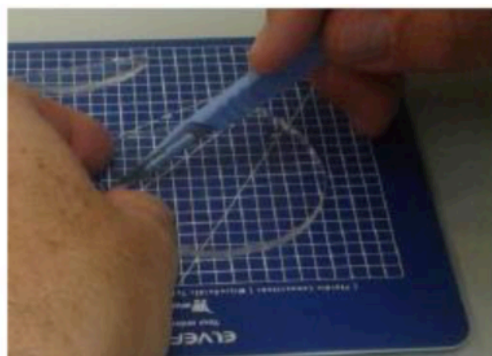
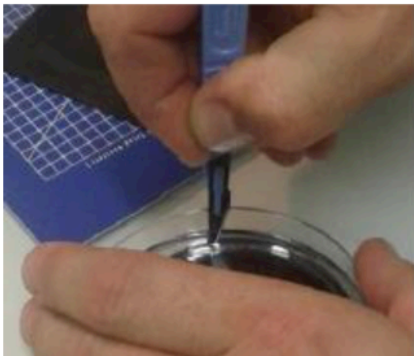
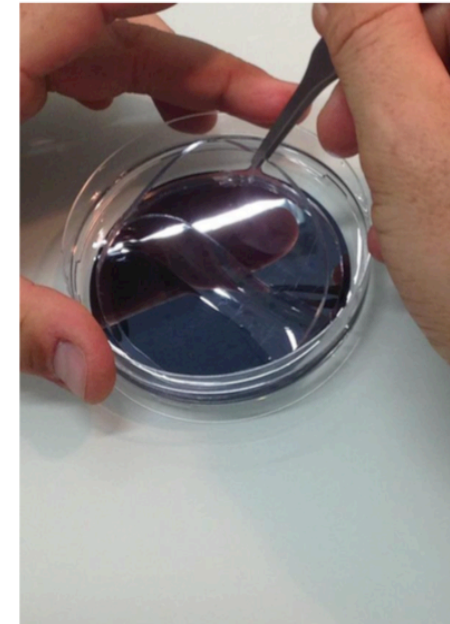
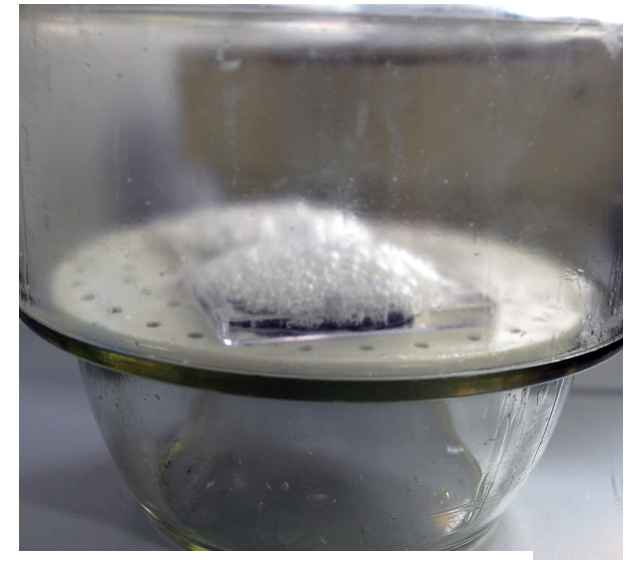
Degaz (vacum or centrifuge)

Baking (70°C for 2 hours)

Extraction

Punching

Bonding

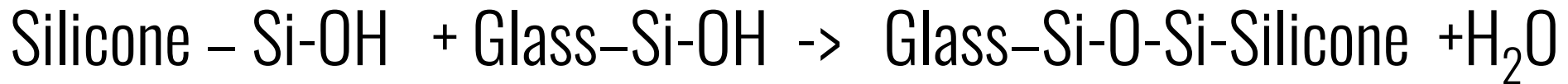
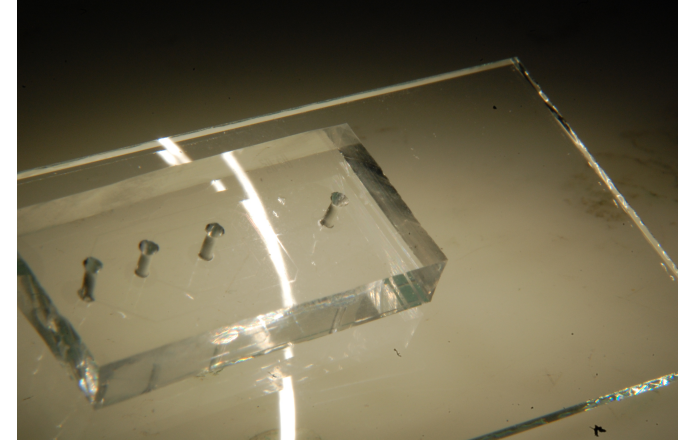


PDMS Bonding

PDMS surface is hydrophobic, composed of $\text{Si}(\text{CH}_3)_3$

Plasma treatment replaces it with $\text{Si}-\text{OH}$ (silanol group)

When two surfaces are plasma activated and enter in contact :

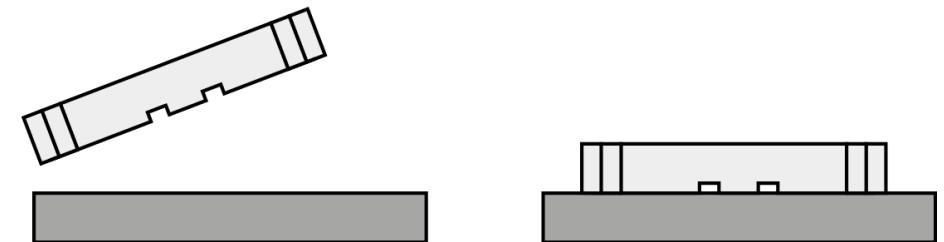
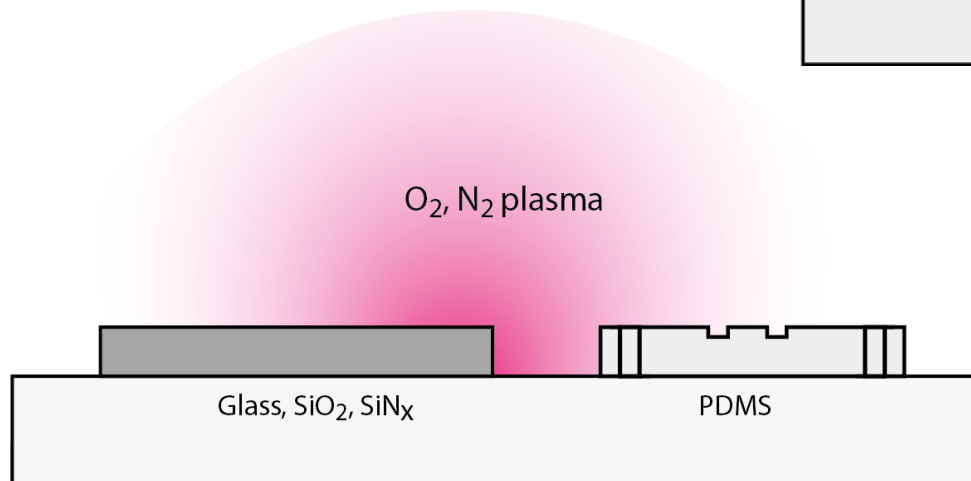
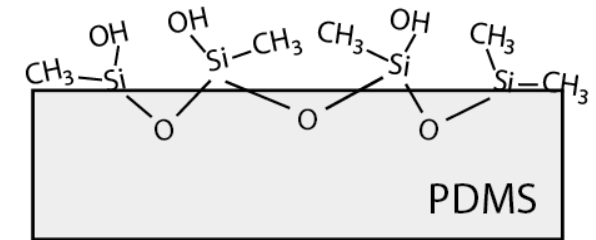
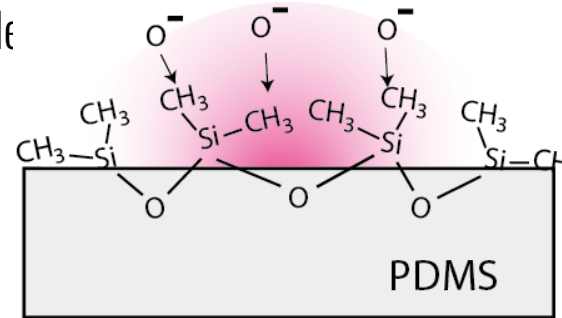


It works with every material containing Si (Glass, PDMS, SiO_2 , Si_3N_4 , ...)

Note : Plasma activation fades in about 20 to 30mn (diffusion non crosslinked chains)

Requires a perfect contact (flatness, dust, particle)

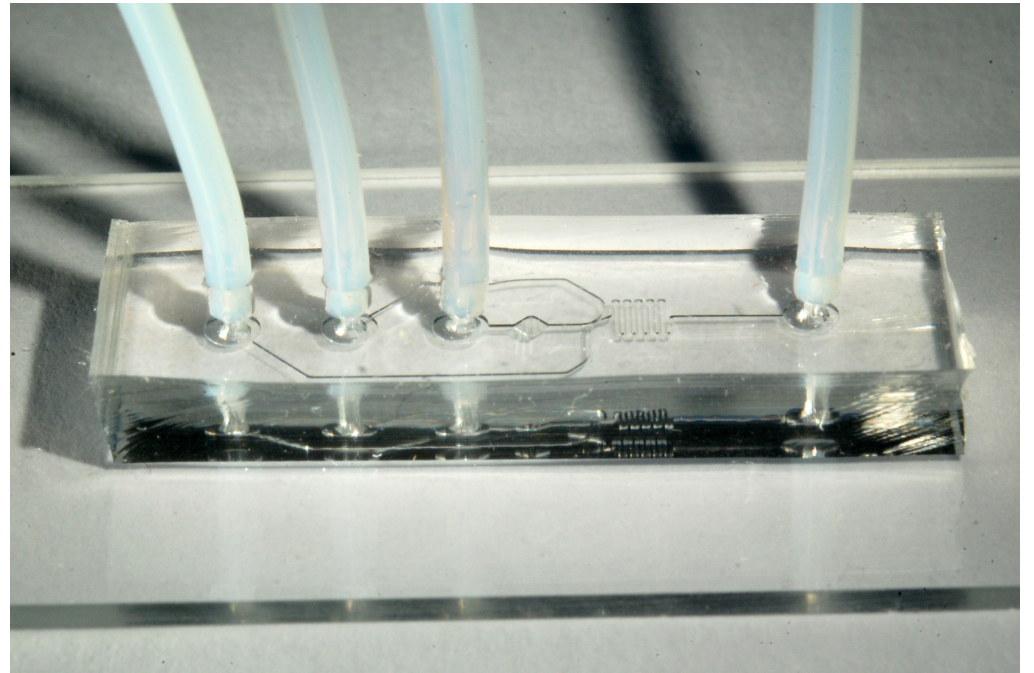
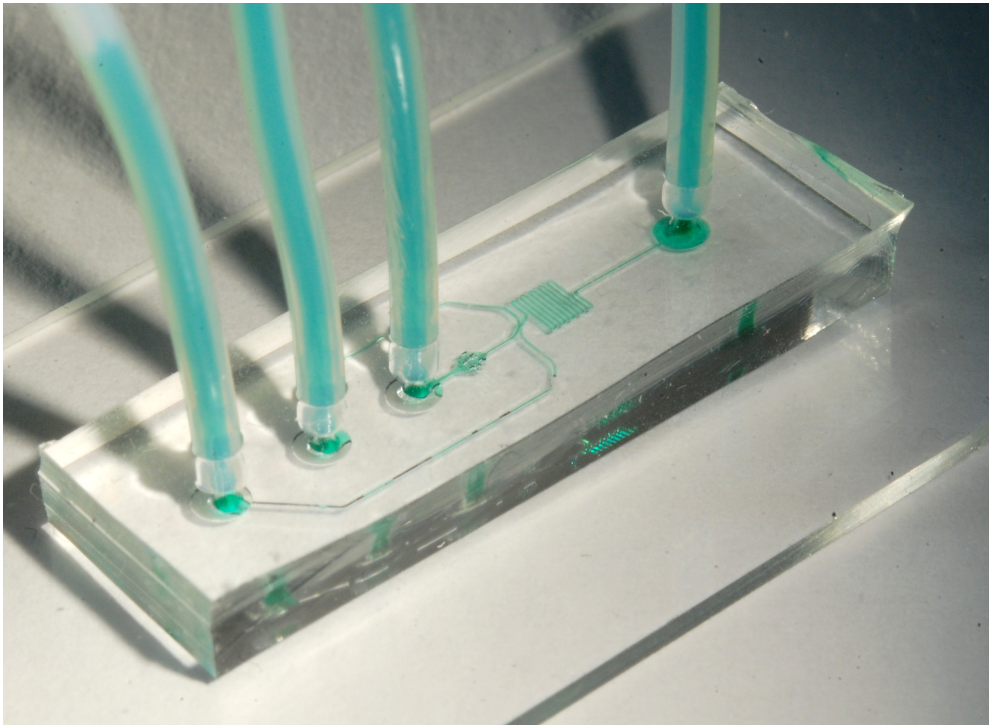
Moisture can be a problem



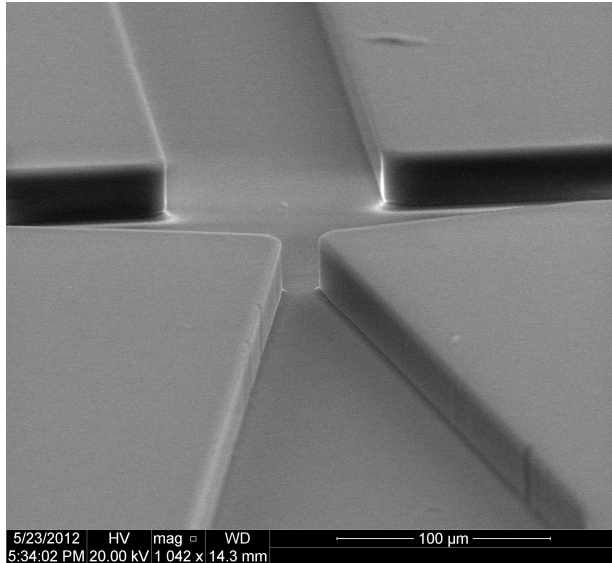
PDMS plasma bonding is strong and irreversible

PDMS

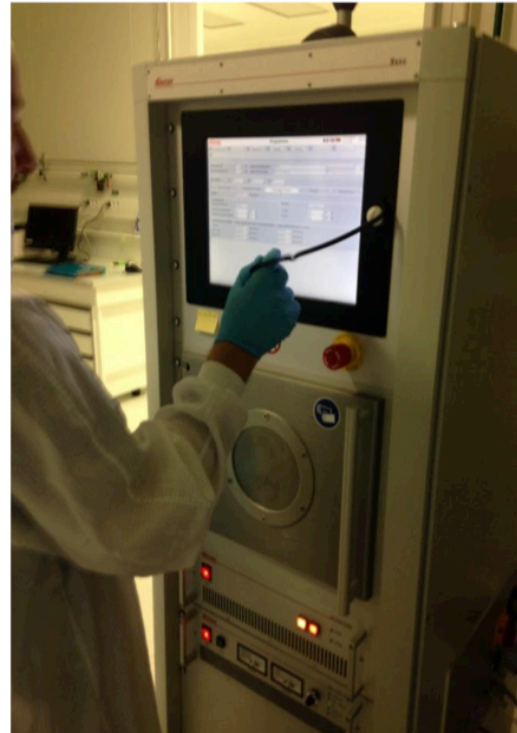
Input Outputs



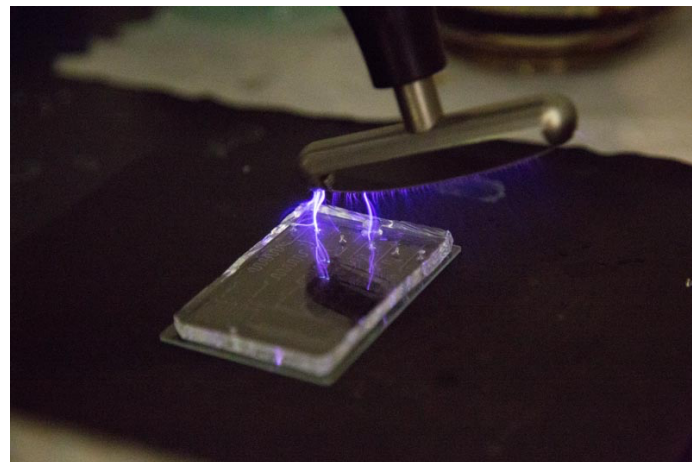
PDMS Bonding



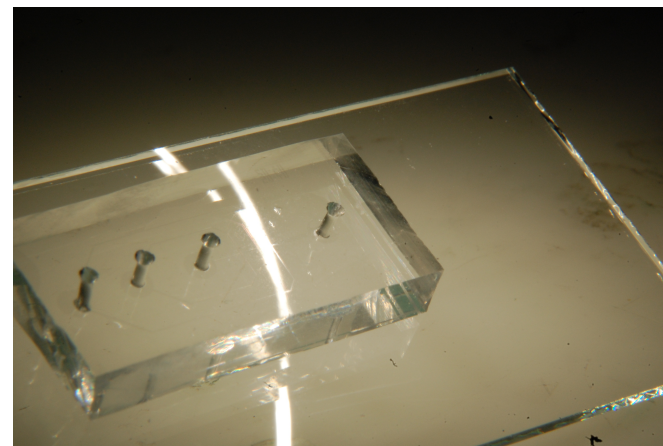
SEM of PDMS circuit



Plasma reactors



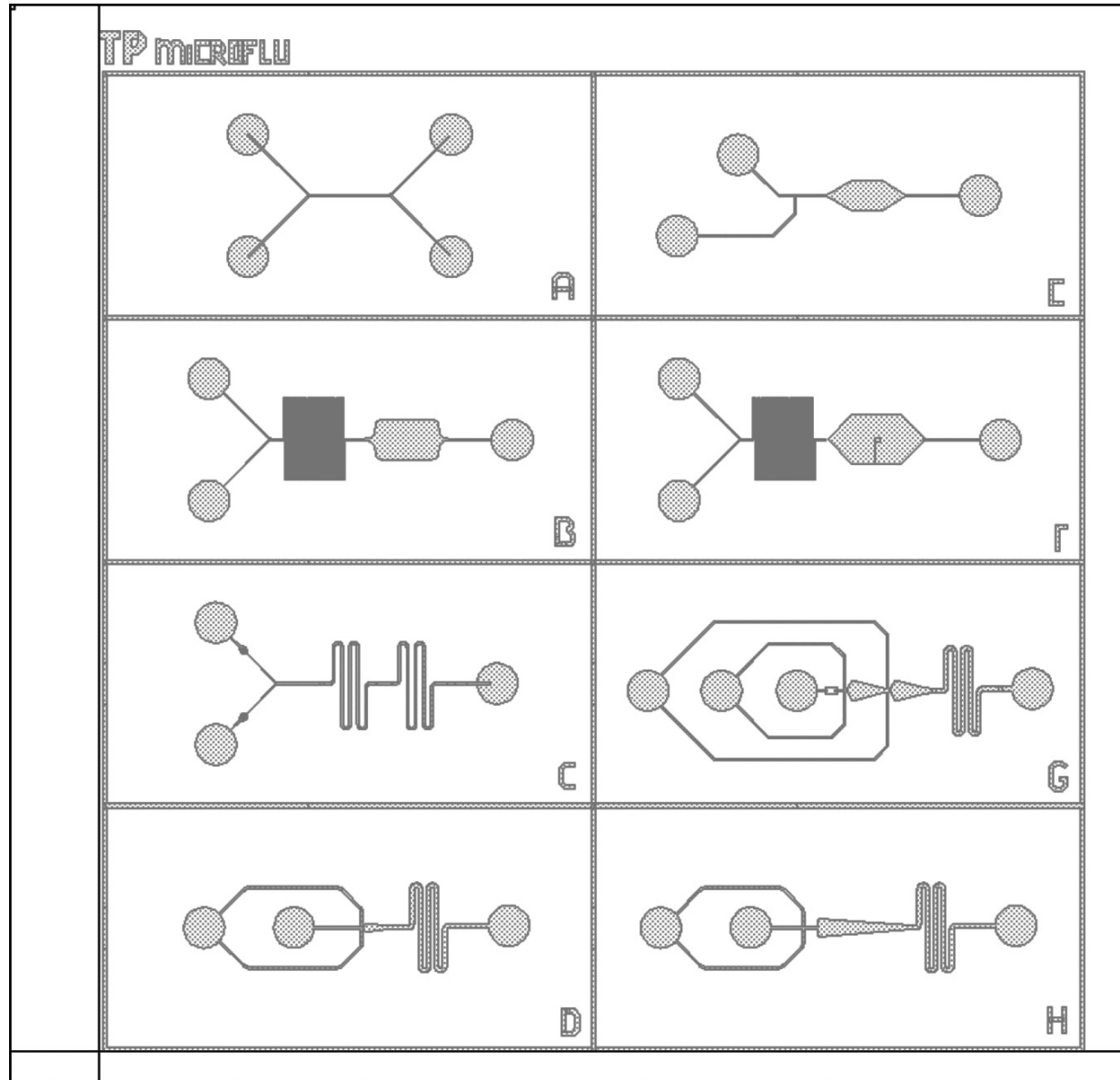
Alternative : Corona discharge



PDMS bonded on glass

PDMS

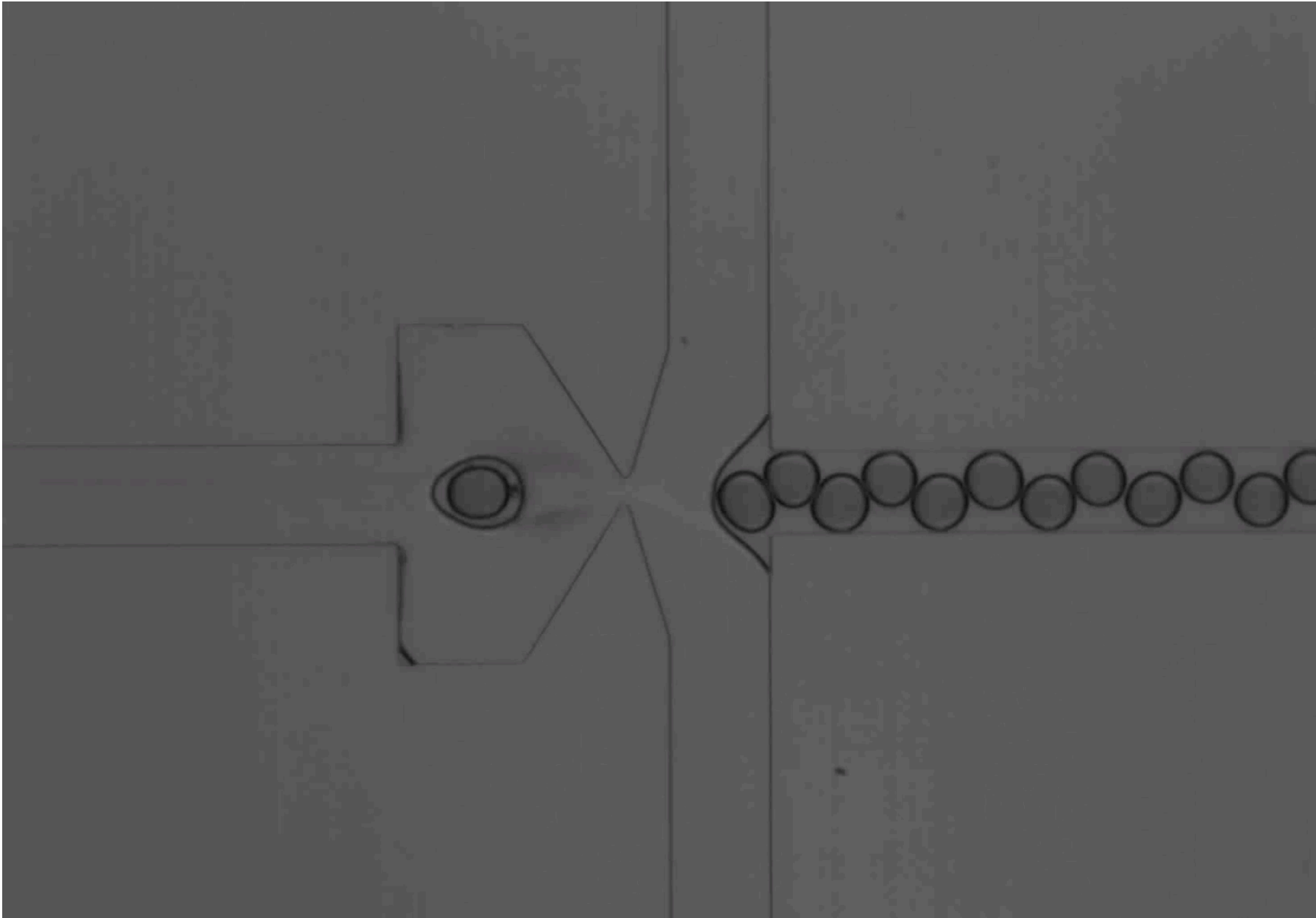
It is then possible to create different structures with PDMS on glass



Lithography mask for the practical work in cleanroom

PDMS

Example of diphasic microfluidic circuit



Microfluidics on Glass

PDMS fits most microfluidics applications but is not adapted for particular applications such as High pressure, harsh conditions...

Glass has some advantages :

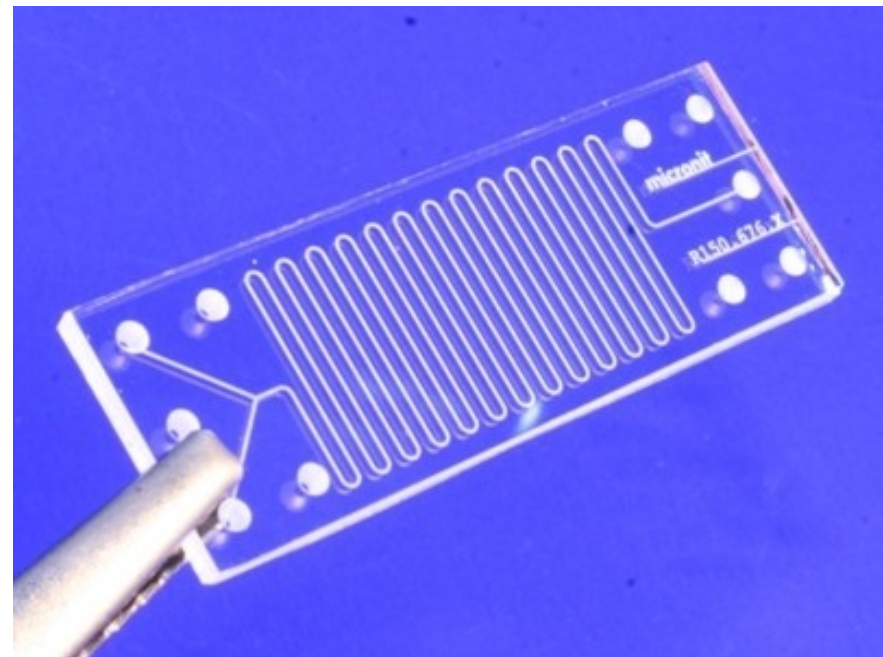
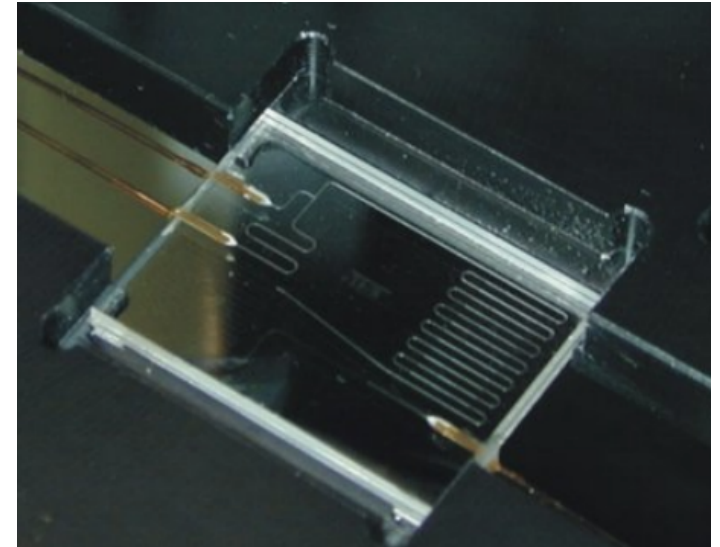
- Hydrophilic
- Chemically inert
- Transparence, no autofluorescence
- hardness
- Electric insulation
- Relative biocompatibility
- Not so expensive

Different types of glass are used

Quartz (crystalline SiO_2)

Soda Lime

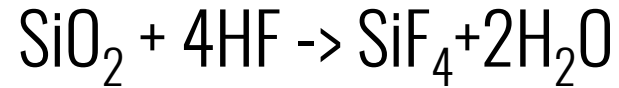
Borofloat (Glass and boron oxide)



Microfluidics on Glass

Glass etching : channel formation in the substrate

- Wet etching : Isotropic + wall roughness (+ultrasound) : low etch rates

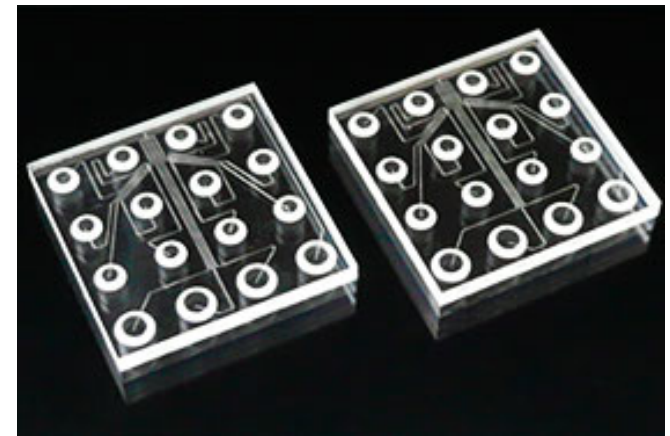
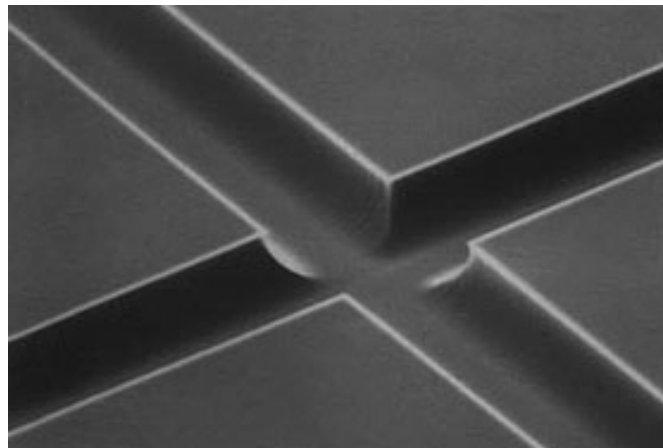
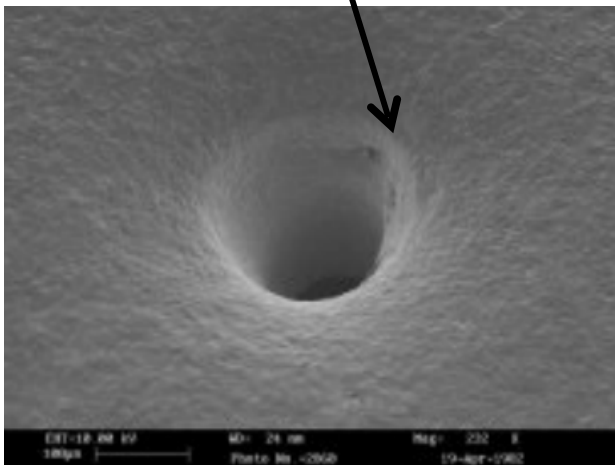
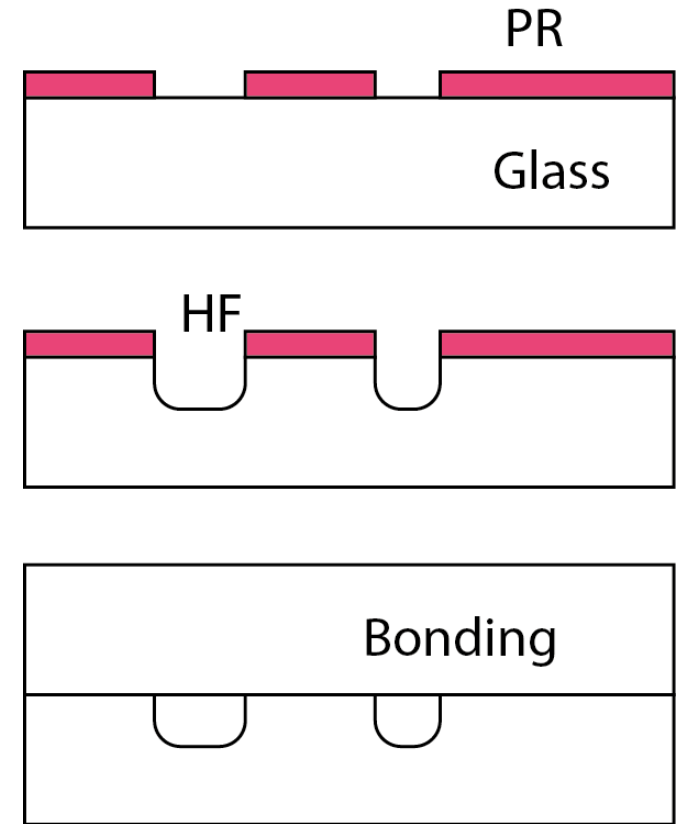


40% HF : 3,4 $\mu\text{m}/\text{min}$, 5% HF : 0.04 $\mu\text{m}/\text{min}$

- Dry etching Fluor gazes plasma etching $\text{CHF}_3, \text{SF}_6, \text{CF}_4 / \text{O}_2$
200 nm/min

- Laser micromachining

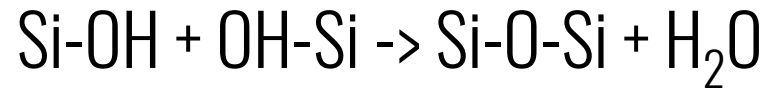
- Powder blasting (Inputs and outputs)



Images : <http://www.imtag.ch/>

Microfluidics on Glass

Glass bonding :

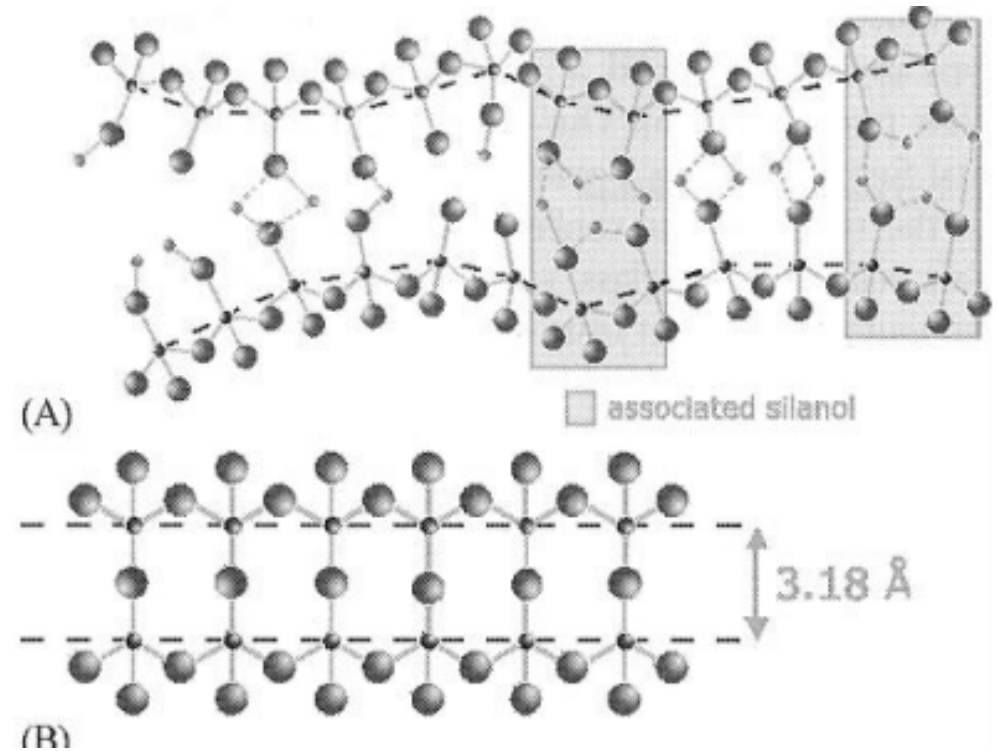


Fusion of of glass/glass interface

Requires a perfect interface : clean, flat, and smooth,

Pressure + $T > T_g$ (550°C - 600°C) for several hours

Glass deformation : aspect ratio of channels



Microfluidics on Glass

Anodic Bonding

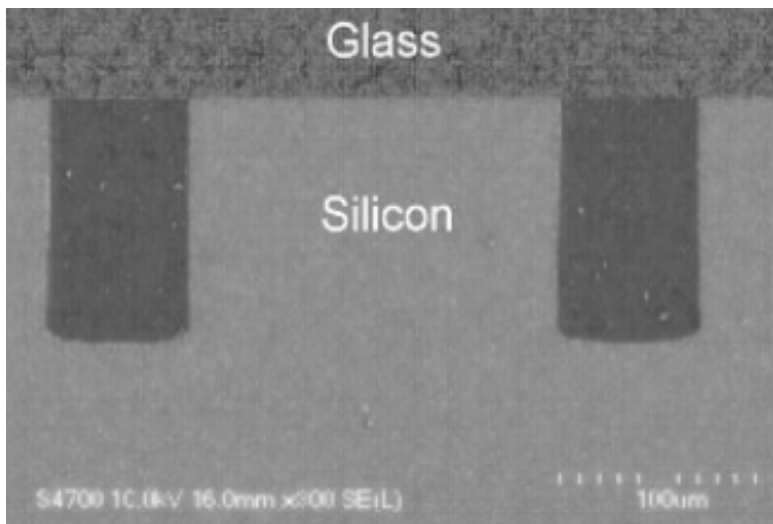
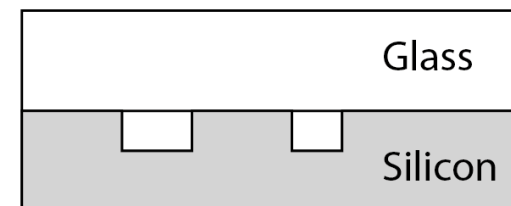
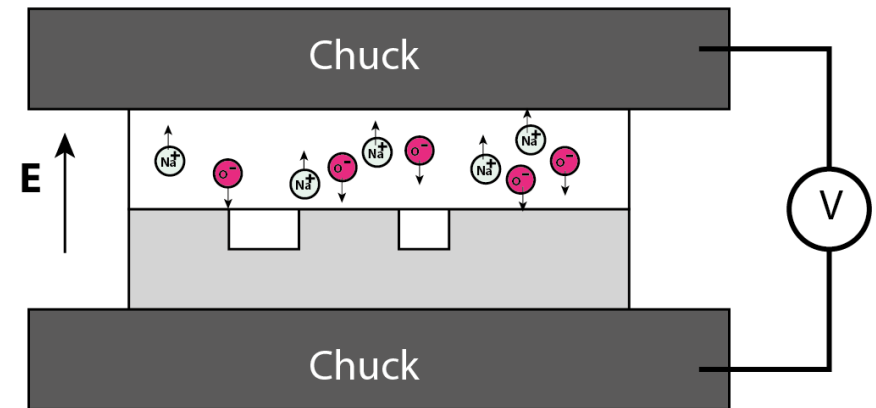
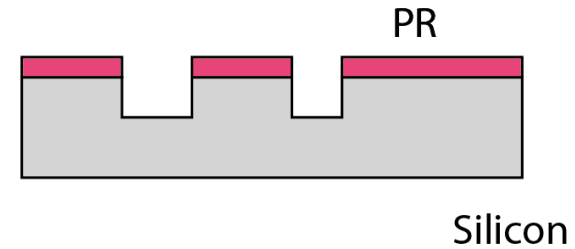
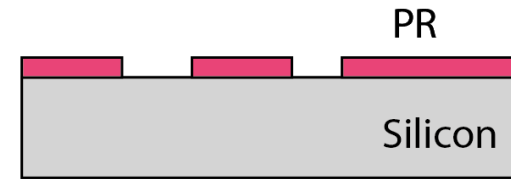
(Pyrex 77400)

200 to 300°C.

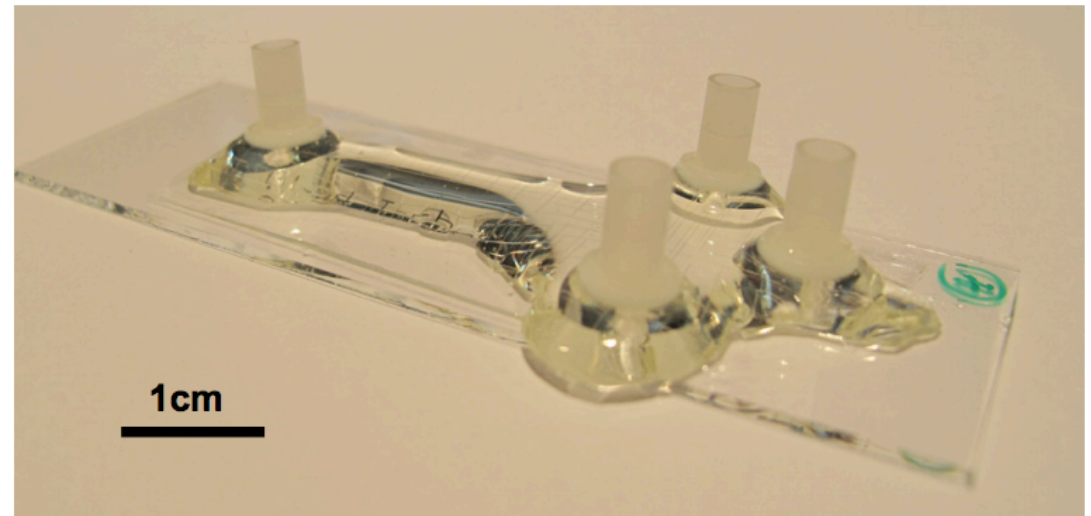
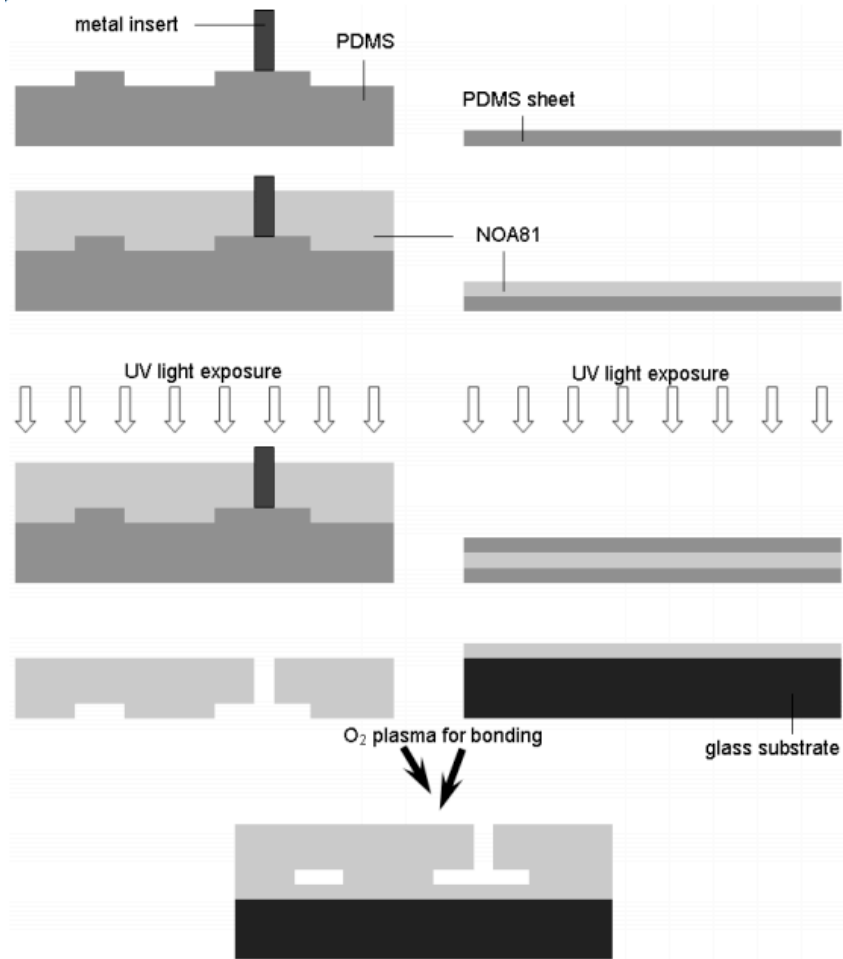
Pressure + Electric field

Ion migration

At the interface : Si oxidation and formation of a SiO_2 layer

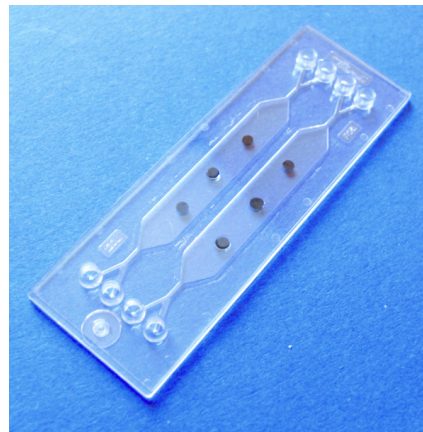
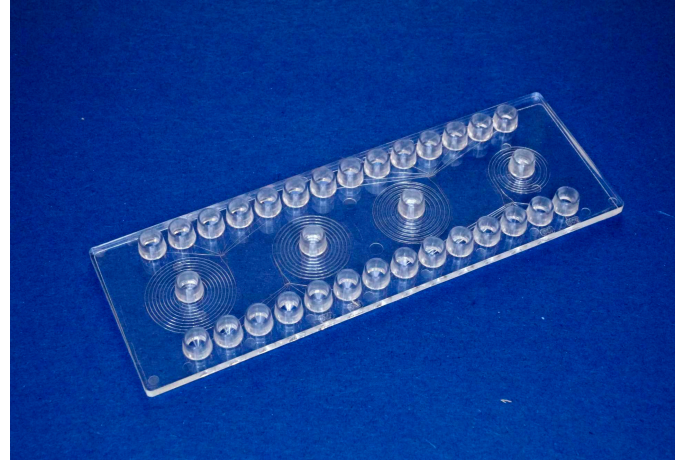
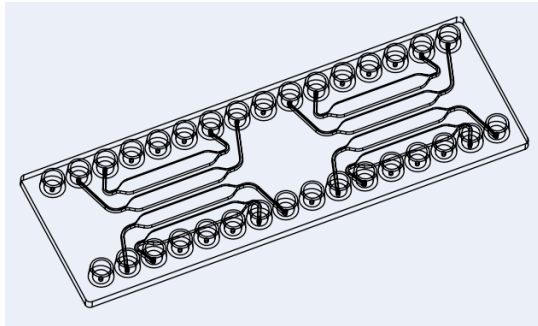
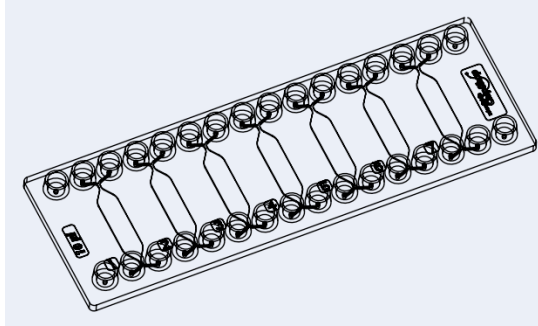


Microfluidics on UV resist



Simple process
Less deformable than PDMS
Requires a positive in PDMS

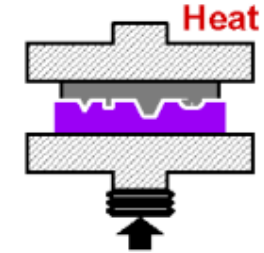
Thermoplastic microfluidics



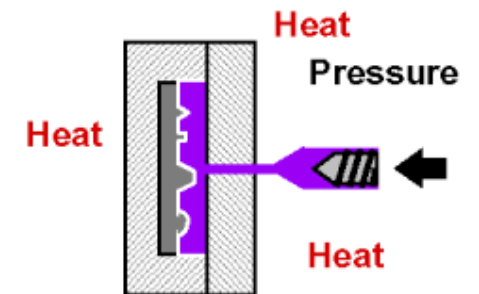
Casting



Hot embossing



Injection Molding



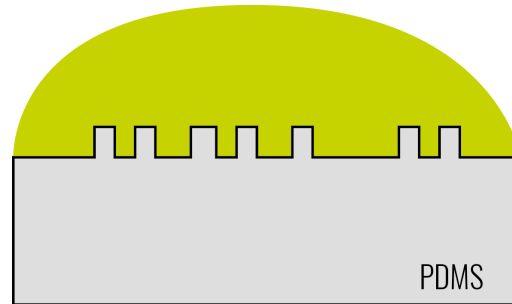
Generic circuits catalog

Hot embossing on metallic substrate

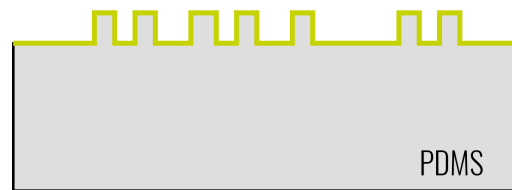
Micro contact printing

PDMS can be used for deposition by contact printing

Surface activation O_2 Plasma



Wetting on PDMS 20mn



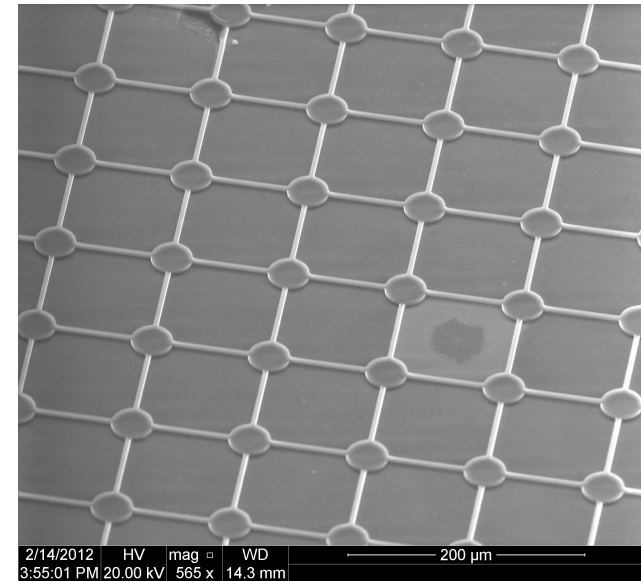
Rinse, blow drying N_2



Stamping



Passivation (PLL-PEG)



Micro contact printing

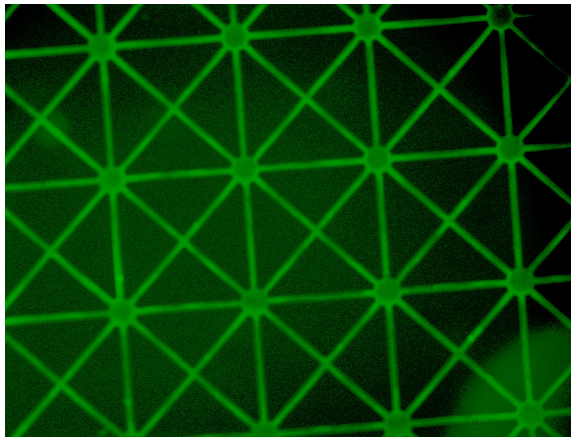
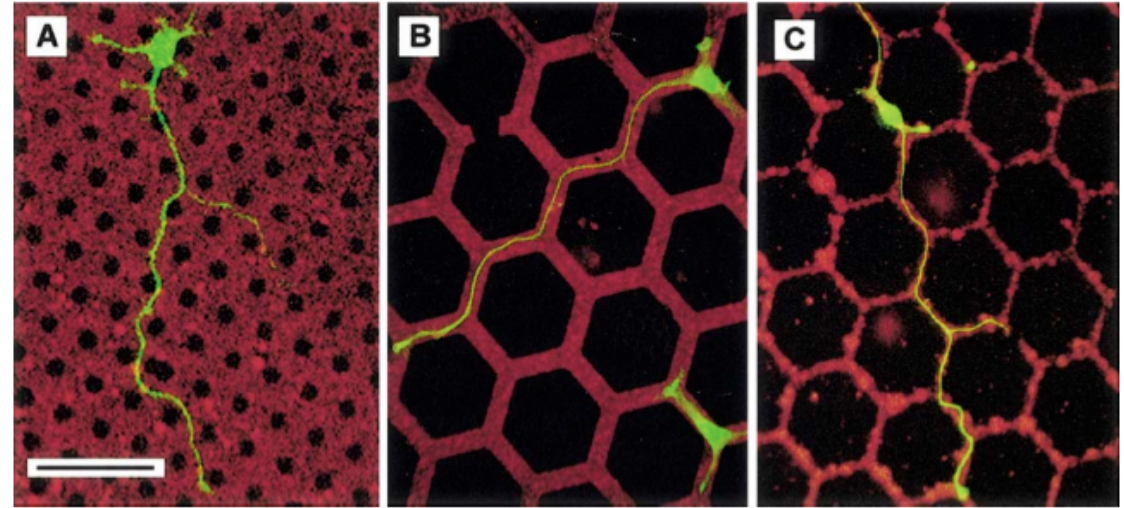
Proteins used for cellular culture

Poly-L-Lysine

Polyornithine

Laminine

Fibronectine



PLL-FITC

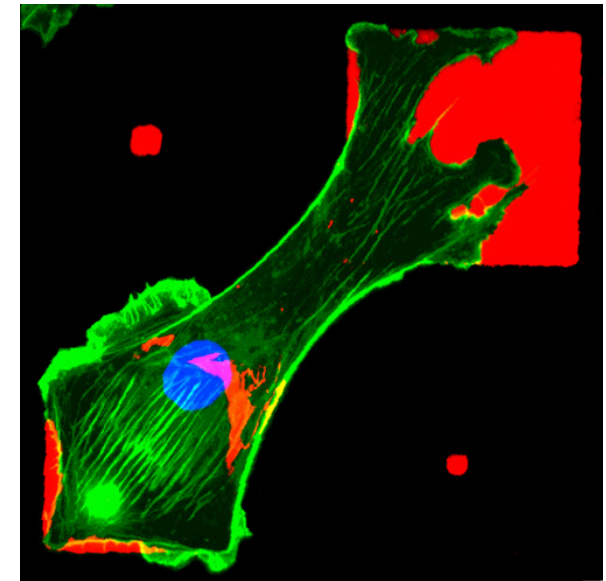
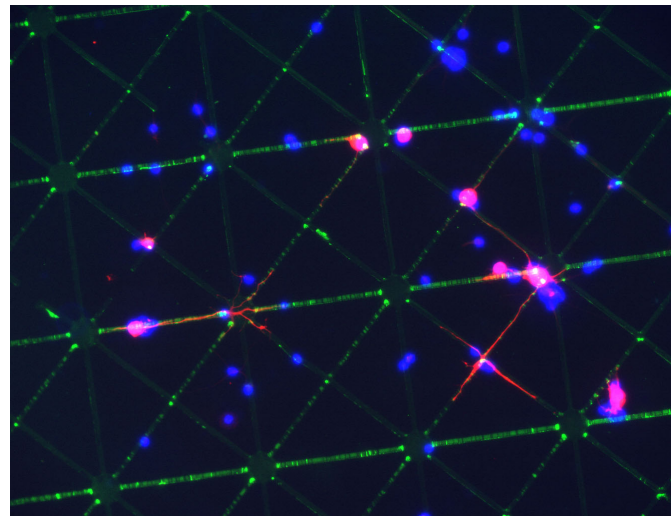


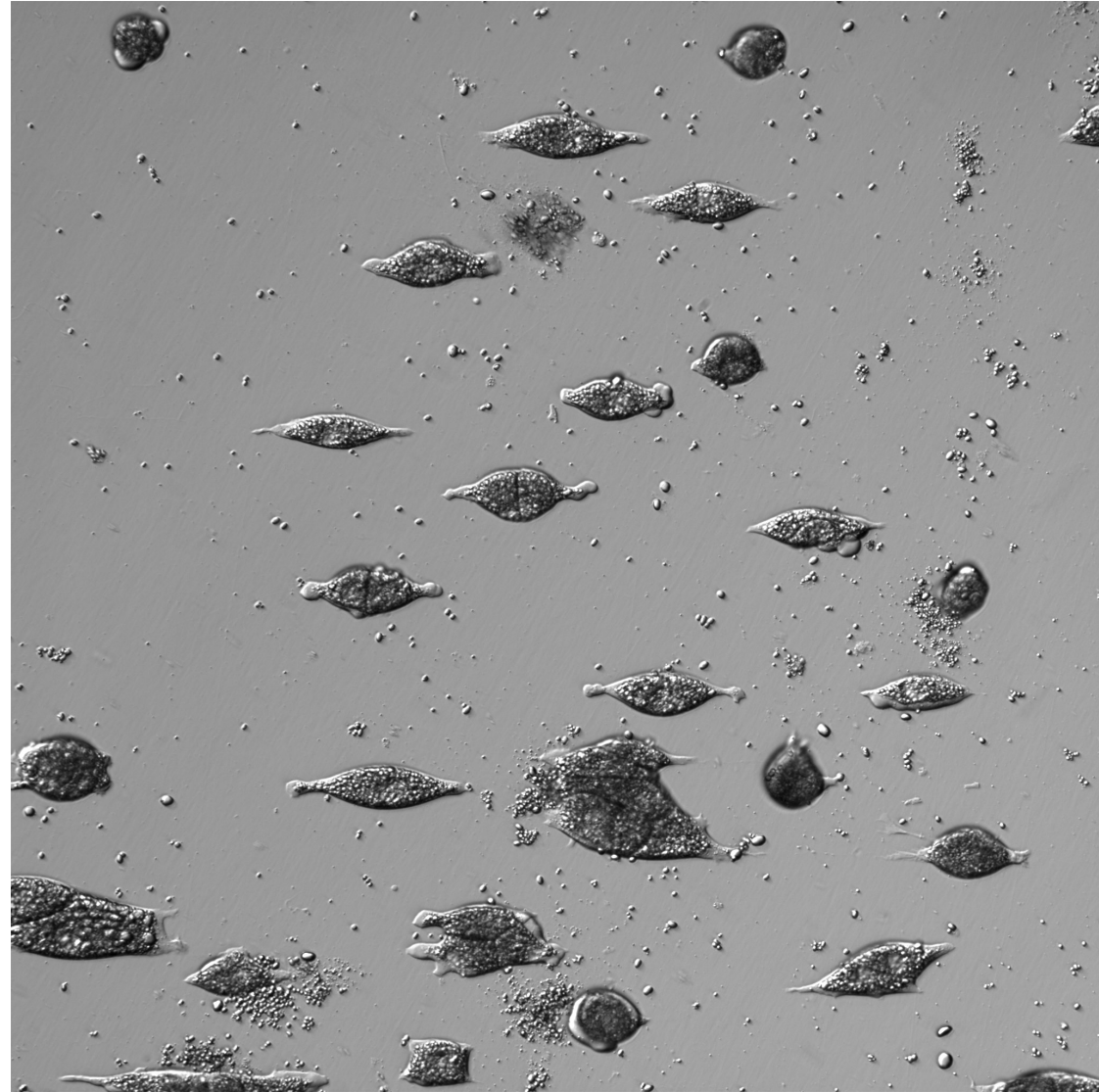
Image : (actin cytoskeleton shown in green; nucleus in blue) initially was plated on a single square (50 x 50 μm) extracellular matrix adhesive island (red) that was created with a microcontact printing technique.

Cliff Brangwynne in the Ingber Lab

Micro contact printing

Experiments with cells adhesion patterns

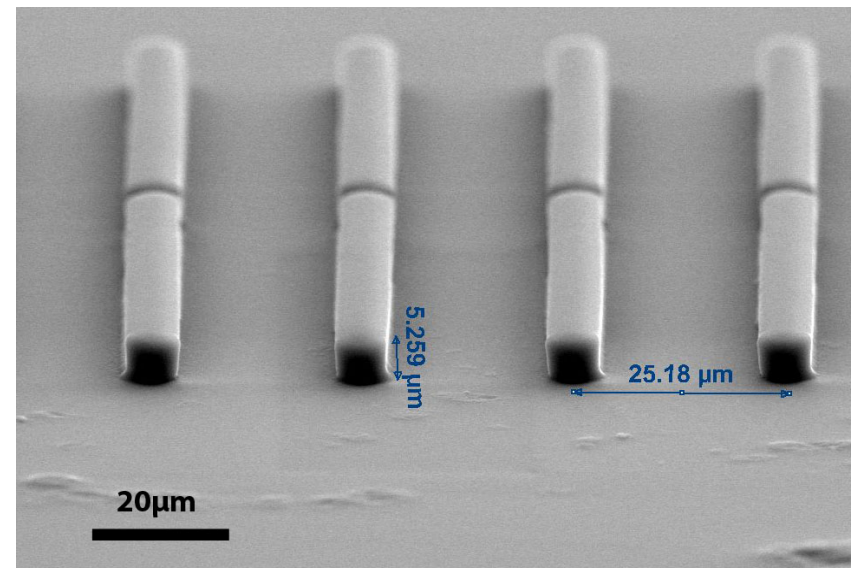
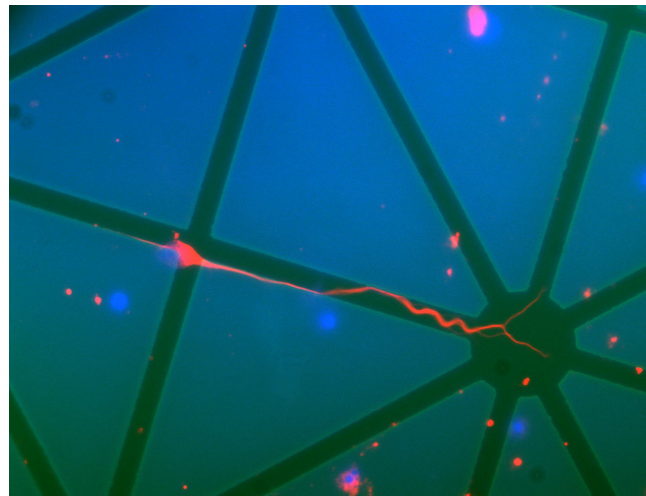
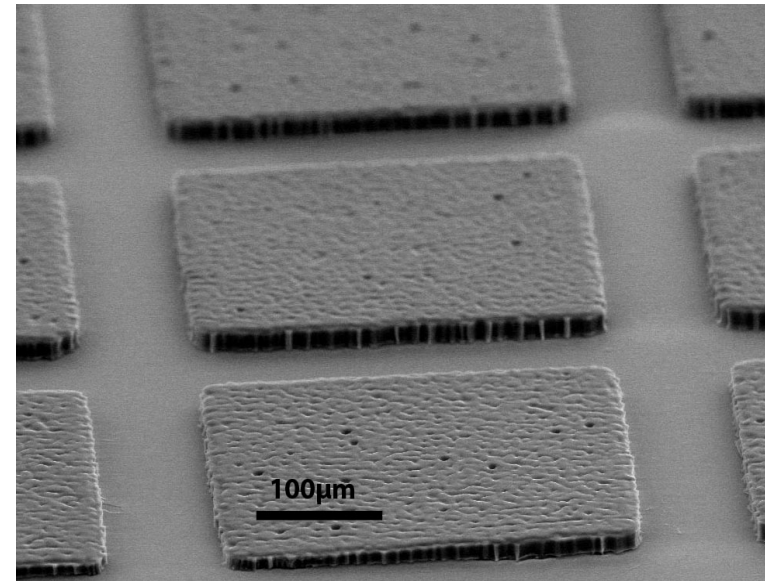
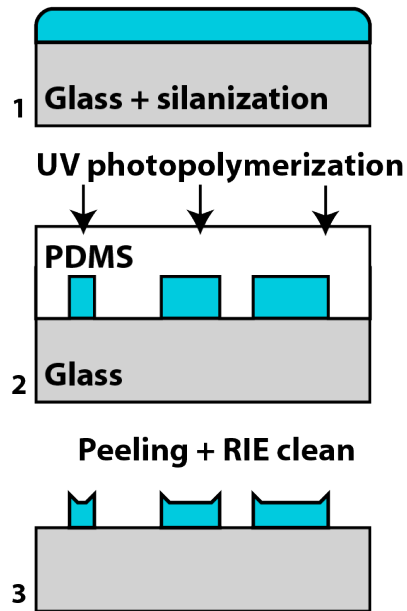
D.Rozema, Fagotto team, CRBM, Montpellier



Micro contact printing PEG-DMA

- Non-immunogenicity
- Non-antigenicity
- Protein rejection
- 2,5 D cell culture pattern
- Confinement
- Cell adhesion selectivity

PEG-DMA Spin coating



Lab on a Chip and Microfluidics

Benoît CHARLOT

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